

# SMARC-sAL28

User Guide Rev. 1.1

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 SMARC-SAL28 – USER GUIDE

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Revision	Brief Description of Changes	Date of Issue	Author
1.0	Initial issue	2020-January-20	hjs
1.1	Word2016 issues	2021-March-31	hjs

## Intended Use

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### **CAUTION**

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Handling and operation of the product is permitted only for trained personnel within a work place that is access controlled. Please follow the "General Safety Instructions" supplied with the system.

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### **NOTICE**

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You find the most recent version of the "General Safety Instructions" online in the download area of this product.

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## Customer Service

As a trusted technology innovator and global solutions provider, Kontron extends its embedded market strengths into a services portfolio allowing companies to break the barriers of traditional product lifecycles. Proven product expertise coupled with collaborative and highly-experienced support enables Kontron to provide exceptional peace of mind to build and maintain successful products.

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## Customer Comments

If you have any difficulties using this user guide, discover an error, or just want to provide some feedback, contact [Kontron support](#). Detail any errors you find. We will correct the errors or problems as soon as possible and post the revised user guide on our website.

## Symbols

The following symbols may be used in this manual

### DANGER

DANGER indicates a hazardous situation which, if not avoided, will result in death or serious injury.

### WARNING

WARNING indicates a hazardous situation which, if not avoided, could result in death or serious injury.

### NOTICE

NOTICE indicates a property damage message.

### CAUTION

CAUTION indicates a hazardous situation which, if not avoided, may result in minor or moderate injury.



Electric Shock!

This symbol and title warn of hazards due to electrical shocks (> 60 V) when touching products or parts of products. Failure to observe the precautions indicated and/or prescribed by the law may endanger your life/health and/or result in damage to your material.



ESD Sensitive Device!

This symbol and title inform that the electronic boards and their components are sensitive to static electricity. Care must therefore be taken during all handling operations and inspections of this product in order to ensure product integrity at all times.



HOT Surface!

Do NOT touch! Allow to cool before servicing.



Laser!

This symbol inform of the risk of exposure to laser beam and light emitting devices (LEDs) from an electrical device. Eye protection per manufacturer notice shall review before servicing.



This symbol indicates general information about the product and the user guide.

This symbol also indicates detail information about the specific product configuration.



This symbol precedes helpful hints and tips for daily use.

## For Your Safety

Your new Kontron product was developed and tested carefully to provide all features necessary to ensure its compliance with electrical safety requirements. It was also designed for a long fault-free life. However, the life expectancy of your product can be drastically reduced by improper treatment during unpacking and installation. Therefore, in the interest of your own safety and of the correct operation of your new Kontron product, you are requested to conform with the following guidelines.

### High Voltage Safety Instructions

As a precaution and in case of danger, the power connector must be easily accessible. The power connector is the product's main disconnect device.

#### ⚠ CAUTION

##### Warning

All operations on this product must be carried out by sufficiently skilled personnel only.

#### ⚠ CAUTION



##### Electric Shock!

Before installing a non hot-swappable Kontron product into a system always ensure that your mains power is switched off. This also applies to the installation of piggybacks. Serious electrical shock hazards can exist during all installation, repair, and maintenance operations on this product. Therefore, always unplug the power cable and any other cables which provide external voltages before performing any work on this product.

Earth ground connection to vehicle's chassis or a central grounding point shall remain connected. The earth ground cable shall be the last cable to be disconnected or the first cable to be connected when performing installation or removal procedures on this product.

### Special Handling and Unpacking Instruction

#### NOTICE



##### ESD Sensitive Device!

Electronic boards and their components are sensitive to static electricity. Therefore, care must be taken during all handling operations and inspections of this product, in order to ensure product integrity at all times.

Do not handle this product out of its protective enclosure while it is not used for operational purposes unless it is otherwise protected.

Whenever possible, unpack or pack this product only at EOS/ESD safe work stations. Where a safe work station is not guaranteed, it is important for the user to be electrically discharged before touching the product with his/her hands or tools. This is most easily done by touching a metal part of your system housing.

It is particularly important to observe standard anti-static precautions when changing piggybacks, ROM devices, jumper settings etc. If the product contains batteries for RTC or memory backup, ensure that the product is not placed on conductive surfaces, including anti-static plastics or sponges. They can cause short circuits and damage the batteries or conductive circuits on the product.

## General Instructions on Usage

In order to maintain Kontron's product warranty, this product must not be altered or modified in any way. Changes or modifications to the product, that are not explicitly approved by Kontron and described in this User Guide or received from Kontron's Technical Support as a special handling instruction, will void your warranty.

This product should only be installed in or connected to systems that meet all necessary technical and specific environmental requirements. This also applies to the operational temperature range of the specific board version, which must not be exceeded. If batteries are present, their temperature restrictions must be taken into account.

In performing all necessary installation and application operations, only follow the instructions supplied by the present User Guide.

Keep all the original packaging material for future storage or warranty shipments. If it is necessary to store or ship the product then re-pack it in the same manner as it was delivered.

Special care is necessary when handling or unpacking the product. See Special Handling and Unpacking Instruction.

## Quality and Environmental Management

Kontron aims to deliver reliable high-end products designed and built for quality, and aims to complying with environmental laws, regulations, and other environmentally oriented requirements. For more information regarding Kontron's quality and environmental responsibilities, visit <http://www.kontron.com/about-kontron/corporate-responsibility/quality-management>.

## Disposal and Recycling

Kontron's products are manufactured to satisfy environmental protection requirements where possible. Many of the components used are capable of being recycled. Final disposal of this product after its service life must be accomplished in accordance with applicable country, state, or local laws or regulations.

## WEEE Compliance

The Waste Electrical and Electronic Equipment (WEEE) Directive aims to:

Reduce waste arising from electrical and electronic equipment (EEE)

Make producers of EEE responsible for the environmental impact of their products, especially when the product become waste

Encourage separate collection and subsequent treatment, reuse, recovery, recycling and sound environmental disposal of EEE

Improve the environmental performance of all those involved during the lifecycle of EEE




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**Environmental protection is a high priority with Kontron.**

**Kontron follows the WEEE directive**

**You are encouraged to return our products for proper disposal.**

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# 1/ Introduction

This manual describes the Smart Mobility Architecture (SMARC) sAL28 (NXP LS1028) board. The Advanced RISC Machines (ARM) based module is equipped with a NXP i.MX7 processor. The dual core SoC take advantage of the optimized power consumption and performance ratio.

The use of this Users Guide implies a basic knowledge of PC hard- and software. This manual is focussed on describing the special features and is not intended to be a standard PC textbook. New users are recommended to study the short installation procedure stated in the following chapter before switching on the power.

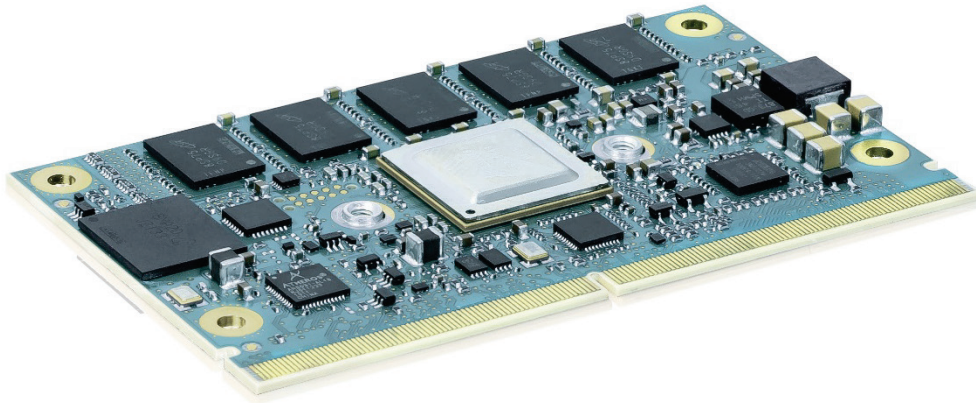
All configuration and setup of the CPU board is either done automatically or manually by the user via the BIOS setup menus.

Latest revision of this manual, datasheet, BIOS, drivers and BSP's (Board Support Packages) can be downloaded from Kontron Web Page.

## 2/ Description

The SMARC-sAL28 is a SMARC half-size module using the NXP's LS1028 processor with dual core ARM. It is designed on the latest SMARC 2.0 specification. The SMARC-sAL28 is a highly integrated, embedded computer board incorporating the edge technology with a dual core SoC from NXP to take advantage of the very optimized power consumption/performance ratio. Due to the integrated Time-Sensitive Networking (TSN) capabilities of the LS1028 and the integrated 4-port Ethernet switch, this board will allow to build very cost effective TSN capable Ethernet gateways for greenfield and brownfield applications.

Figure 1: Half-size Card with SMARC interface



### 2.1. SMARC™ Computer-on-Modules

The SMARC™ standard was developed especially for new modules with ARM- and SoC-processors. Boards with this interfaces are characterized by the extremely flat form factor. The SMARC or MXM 3.0 connector comes with 314 pins and a construction height of just 4.3 millimeters. The connector is also available in a shock- and vibration-resistant version for rough environmental conditions.

Furthermore, the standard integrates dedicated interfaces for the latest ARM, x86 and SoC processors like LVDS, 24-bit RGB and HDMI support. OEMs profit from minimized design effort and low Bill of Material (BoM) costs. SMARC™ defines two different module sizes in order to offer a high level of flexibility regarding different mechanical requirements.

Main characteristics of the SMARC-sAL28 are:

- ▶ Dual-Core Cortex A-72 on a SMARC short size form factor
- ▶ Based on LS1028 from NXP – one SKU with configurable Serialiser/Deserialiser SERDES lines (5 W target TDP)
- ▶ Up to 4 GB DDR3L non-ECC and ECC memory down, ECC as default, 8 GbE as option
- ▶ One PCIe line can be used as QSGMII port to drive 4x 1 GB TSN capable Ethernet ports
- ▶ 3D GPU
- ▶ DP support (default)
- ▶ LVDS Display support (resistor option)
- ▶ Alternative eDP (resistor option)
- ▶ 2x Gigabit Ethernet, Wake on LAN (WoL) support, TSN capable
- ▶ Support for Audio and common features (SPI, I2C, SMB etc.)
- ▶ Chip integrated security solution support
- ▶ Full industrial grade temp. range E2 (-40°C up to +85°C) for standard SKUs, commercial version possible
- ▶ eMMC flash onboard
- ▶ Optional APPROTECT (security chip) support on request, more information under <https://www.kontron.de/products/solutions/security/approprotect.html>

## 2.2. Standard Variants

Following standard variants are available:

Table 1: Product Numbers of SMARC-sAL28

Product Number	Board	Description
51011-0208-13-2-2	SMARC-sAL28, LS1028 dual, 2E/8S, NW 2	SMARC with NXP LS1028, 1,3 GHz dual core; 2 GB DDR3L ECC, 8 GB eMMC SLC, Networkconfig 2, 2x PCIe, audio, DP, industrial temperature
51011-0408-13-2-3	SMARC-sAL28, LS1028 dual, 4E/8S, NW 3	SMARC with NXP LS1028, 1,3 GHz dual core; 4 GB DDR3L ECC, 8 GB eMMC SLC, Networkconfig 3, 2x PCIe, audio, DP, industrial temperature
51011-0432-13-2-4	SMARC-sAL28, LS1028 dual, 4E/32S, NW 4	SMARC with NXP LS1028, 1,3 GHz dual core; 4 GB DDR3L ECC, 32 GB eMMC SLC, Networkconfig 4, 2x PCIe, no audio, DP, industrial temperature

## 2.3. Network Configuration Options

Table 2: Product Variants of SMARC-sAL28

Variant	Description
<b>Network Variant 1</b> (Single PHY module, optional)	<ul style="list-style-type: none"> <li>▶ Available on customer request</li> <li>▶ SMARC with NXP LS1028, 1.3 GHz dual core; 2 GB DDR3L ECC, 8 GB eMMC SLC, DP, industrial temperature</li> <li>▶ GBE0 PHY connected to RGMII (L0) to CPU (not TSN capable)</li> <li>▶ GBE1 not connected on module, GBE1 could be used on custom carrier to support 2.5 GBE</li> <li>▶ no audio</li> <li>▶ "TSN" variant, although GBE0 is not TSN capable, thus the TSN function needs a TSN carrier.</li> <li>▶ TSN-on-carrier (board provides the 4 TSN capable ports on PCIe D by QSGMII lane)</li> <li>▶ 4 lanes available towards the carrier</li> <li>▶ Possible PCIe options (lane AB/CD), one of               <ul style="list-style-type: none"> <li>▶ 2x PCIe x1</li> <li>▶ 1x PCIe x1 + 1x SATA</li> <li>▶ 1x PCIe x2 + 1x PCIe x1</li> <li>▶ 2x PCIe x2 (no TSN-On-Carrier)</li> <li>▶ 1x PCIe x4, with custom carrier, because special lane order (CDAB instead of ABCD), (no TSN-On-Carrier)</li> </ul> </li> </ul>
<b>Network Variant 2</b> (Dual TSN port module)	<ul style="list-style-type: none"> <li>▶ SMARC with NXP LS1028, 1.3 GHz dual core; 2 GB DDR3L ECC, 8 GB eMMC SLC, DP, industrial temperature</li> <li>▶ GBE0 PHY connected to SGMII (L0) to the internal switch</li> <li>▶ GBE1 PHY connected to SGMII (L1) to the internal switch</li> <li>▶ no direct network operation without switch up and running</li> <li>▶ Dual port TSN Endpoint (no need of additional PHYs on Carrier)</li> <li>▶ Audio</li> <li>▶ no QSGMII lane</li> <li>▶ Possible PCIe options (lane A/B), one of               <ul style="list-style-type: none"> <li>▶ 2x PCIe x1</li> </ul> </li> </ul>

Variant	Description
	<ul style="list-style-type: none"> <li>▶ 1x PCIe x2</li> <li>▶ 1x PCIe x1 + 1x SATA</li> </ul>
<b>Network Variant 3 (Single PHY module)</b>	<ul style="list-style-type: none"> <li>▶ SMARC with NXP LS1028, 1.3 GHz dual core; 4 GB DDR3L ECC, 8 GB eMMC SLC, DP, industrial temperature</li> <li>▶ GBE0 PHY connected to SGMII (L0) to CPU (TSN capable)</li> <li>▶ GBE1 PHY not connected, GBE1 could be used on custom carrier to support 2.5 GBE</li> <li>▶ 5 ports in total</li> <li>▶ audio</li> <li>▶ TSN-on-Carrier (board provides the 4 TSN capable ports on PCIe D by QSGMII lane)</li> <li>▶ Possible PCIe options (lane A/B), one of               <ul style="list-style-type: none"> <li>▶ 2x PCIe x1</li> <li>▶ 1x PCIe x2</li> <li>▶ 1x PCIe x1 + 1x SATA</li> </ul> </li> </ul>
<b>Network Variant 4 (Dual PHY module)</b>	<ul style="list-style-type: none"> <li>▶ SMARC with NXP LS1028, 1.3 GHz dual core; 4 GB DDR3L ECC, 32 GB eMMC SLC, DP, industrial temperature</li> <li>▶ GBE0 PHY connected to SGMII (L0) to CPU (TSN capable)</li> <li>▶ GBE0 PHY could be connected to switch</li> <li>▶ GBE1 connected to RGMII to CPU</li> <li>▶ 6 ports in total</li> <li>▶ no audio</li> <li>▶ TSN-on-Carrier (board provides the 4 TSN capable ports on PCIe D by QSGMII lane)</li> <li>▶ Possible PCIe options (lane A/B), one of               <ul style="list-style-type: none"> <li>▶ 2x PCIe x1</li> <li>▶ 1x PCIe x2</li> <li>▶ 1x PCIe x1 + 1x SATA</li> </ul> </li> </ul>

Following accessories are available:

- ▶ SMARC 2.0 Evaluation Carrier
- ▶ SMARC Starter Kit
- ▶ KBOX-A-230-LS, including a SMARC-sAL28 Module and a S1914 Carrier exposing the TSN switch Interfaces

## 2.4. SMARC-sAL28 Feature Set

Table 3: SMARC-sAL28 Feature Set

SMARC™ Feature specification	SMARC™ Specification Maximum Number Possible	SMARC-sAL28 Feature support	Description
LVDS Display support	2	2	LVDS option disabled Default option is DP
CSI Camera support	2	No	
USB Interface	6x USB 2.0 with 2x USB 3.0 included	6x USB 2.0 with 1x USB 3.0 included	USB0 without OTG support USB3 with USB 3.0 and OTG support
PCIe Interface	4	2	maximum 2 PCIe controller
GbE Interface	2	Yes	
SDIO Interface	1	Yes	
SPI Interface	2	Yes	Each bus with one chip select at standard modules
I2S Interface	2	1	
I2C Interface	5	3	I2C_PM, I2C_GP, I2C_LCD
CAN	2	2	Second CAN interface as option with abandonment of one I2C interface



## 3/ System Specifications

### 3.1. Component Main Data

The table below summarizes the features of the motherboard.

Table 4: Component Main Data

SMARC-sAL28	
<b>Form factor</b>	Smart Mobility Architecture (SMARC) Hardware with 82 mm x 50 mm, max. thickness 6 mm
<b>Processor</b>	NXP LS28 Layerscape SoC 1.3 GHz, 488 balls FC-BGA, 17x17 mm, 28 nm CMOS
<b>Memory</b>	DDR3L memory down. Maximum DDR3L memory size 8 GB. Standard products with 2 GB and 4 GB are available. For cost reductions lower memory sizes are possible.
<b>Boot Flash</b>	2 MB to 32 MB SPI NOR flash
<b>Bootloader/BIOS</b>	U-Boot Bootloader, Flash for Bootloader connected on SPI1(eSPI).
<b>embedded Multimedia Card (eMMC)</b>	8 GB pSLC and 32 GB pSLC on standard products option for up to 64GB pSLC
<b>EEPROM</b>	24C32, 4k x 8 (32 kbit)
<b>Temperature Monitoring</b>	Thermal Monitoring Unit (TMU) with +/- 5°C accuracy (CPU internal) Thermal sensor measurement temperature range is 0°C to 125°C.
Onboard Controllers	
<b>Ethernet Controller</b>	2x 1 GBE PHY Qualcomm AR8031-AL, WOL support 1st PHY via SGMII or RGMII BOM option 2nd PHY as BOM option via SGMII
<b>Watchdog</b>	CPU internal watchdog CPLD watchdog for WDT_TIME_OUT#
<b>RTC</b>	High accuracy (+/-3 ppm) Low power consumption: current consumption typical below 1 µA
<b>USB HUB</b>	7 port USB HUB Microchip USB2517I
<b>Display bridge</b>	Optional: Display Port to LVDS converter PTN3460I
<b>System Management Controller</b>	CPLD Intel/Altera MAX V 5M570Z
<b>Security</b>	Optional: APPROTECT Key 1504-03 connected via USB, no SPI connection
<b>Power management</b>	CPLD controls payload power down state
<b>Operating System Support</b>	Linux Yocto Buildroot ( <a href="https://github.com/kontron/buildroot-external-smarc-sal28">https://github.com/kontron/buildroot-external-smarc-sal28</a> ) other Operating Systems on customer request
Interfaces via Smarc I/O	
<b>USB</b>	USB0, USB1, USB2, USB3, USB4, USB5: USB Standard 2.0 USB3: USB Standard 3.1 GEN1 with OTG support
<b>PCIe</b>	4x configurable SERDES lines. Line A and B always present. C and D either used for on module LAN PHYs or as SGMII/XGMII on the carrier (resistor BOM options) Up to 2x PCIe controller
<b>Audio</b>	I2S0

<b>Display</b>	Display port as standard option, FHD (1920x1080) and UHD (3840x2160) Optional: Dual channel LVDS up to 1920x1200 with NXP PTN3460I
<b>SD-Card</b>	1x SDIO
<b>UART</b>	SER0 with RTC/CTS hardware flow control to CPU SER1, SER2 RX/TX
<b>Serial Peripheral Interface (SPI0)</b>	One chip select available at standard module Optional: second chip select possible with abandonment of USB3 power control from CPU
<b>eSPI/SPI1</b>	XSPI_A with CS0#, CS1# – CS0# to module SPI-flash (default) Optional: CS0# to edge Connector (for Carrier uboot booting without SPI flash on module) ALERT0#, ALERT1#, SPI_RESET# from CPLD
<b>GPIO</b>	12 GPIOs
<b>CAN</b>	1x CAN Optional: Second CAN interface with abandonment of one I2C interface
<b>Power</b>	
<b>Consumption</b>	Maximum Power consumption of the board is estimated to 15 W
<b>Input Voltage</b>	Wide range VCC 3.0 V to 5.25 V vripple_p-p (0-20 MHz) = 200 mV 0.1 – 20 ms input voltage rise ramp to 10% nominal VCC
<b>Miscellaneous</b>	
<b>Panel Signal</b>	Display Port Optional: dual channel LVDS or eDP
<b>Features On Request</b>	2x PCIe x2 or 1x PCIe x4 configuration eMMC 5.1 Flash onboard up to 64 GByte pSLC, up to 128 GByte (MLC) Dual Channel LVDS or eDP instead of DP

## 3.2. Environmental Conditions

Table 5: Environmental Conditions

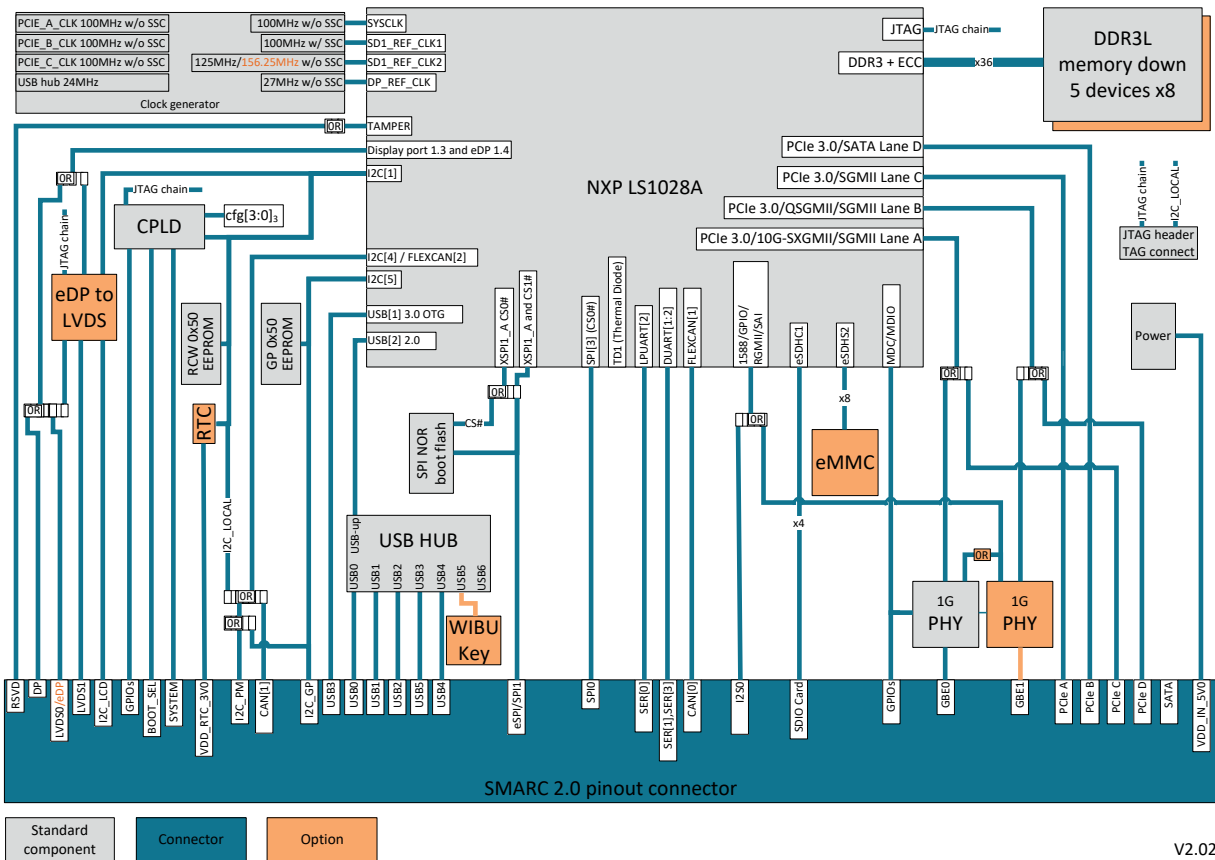
<b>Operating</b>	<ul style="list-style-type: none"> <li>▶ industrial: -40°C to 85°C</li> <li>▶ relative humidity (non-condensing) 10% to 93% at 40°C (acc. to IEC 60068-2-78)</li> </ul>
<b>Storage</b>	<ul style="list-style-type: none"> <li>▶ industrial grade: -40°C to +85°C</li> <li>▶ relative humidity (non-condensing) 10 % to 93 % at 40°C (acc. to IEC 60068-2-78)</li> </ul>
<b>Electromagnetic Compatibility (EMC)</b>	<p>according to</p> <ul style="list-style-type: none"> <li>▶ EN 55032:2015 Electromagnetic compatibility of multimedia equipment - Emission requirements (CISPR 32:2015); German version EN 55032:2015</li> <li>▶ EN 55024:2010 + A1:2015 Information technology equipment - Immunity characteristics - Limits and methods of measurement (CISPR 24:2010 + Cor.:2011 + A1:2015); German version EN 55024:2010 + A1:2015</li> </ul>
<b>CE</b>	<p>CE according to</p> <ul style="list-style-type: none"> <li>▶ EN62368-1:2014 + AC:2017</li> <li>▶ EN610000-6-3:2007 + A1:2011</li> <li>▶ CISPR 32: Edition 1.0 2012-01, class B, 1-6 GHz</li> <li>▶ EN55032:2015</li> <li>▶ EN55024:2010 + A1:2015</li> </ul>
<b>UL</b>	according to IEC 62368-1 (ed.2)
<b>Shock</b>	<ul style="list-style-type: none"> <li>▶ Pulse: half sinus</li> <li>▶ Period: 11 ms</li> <li>▶ Acceleration: 15 g</li> <li>▶ Cycles: three shocks per axis, three axes</li> </ul>

<b>Vibration</b>	<ul style="list-style-type: none"><li>▶ Sinus from 10 Hz -3000 Hz</li><li>▶ Amplitude: 10 Hz-57,6 Hz: +/- 0,15 mm</li><li>▶ Acceleration: 57,6 Hz – 3000Hz: 2 g</li><li>▶ Cycles: 10 per axis, three axes</li></ul>
<b>Theoretical MTBF</b>	estimated 10 years at 40°C
<b>RoHS II Compliance</b>	The product is RoHS II compliant

### 3.3. Functional Block Diagram

The block diagram shows all available interfaces on the sAL28 module.

Figure 2: Block Diagram



V2.02

## 4/ Board and Connectors

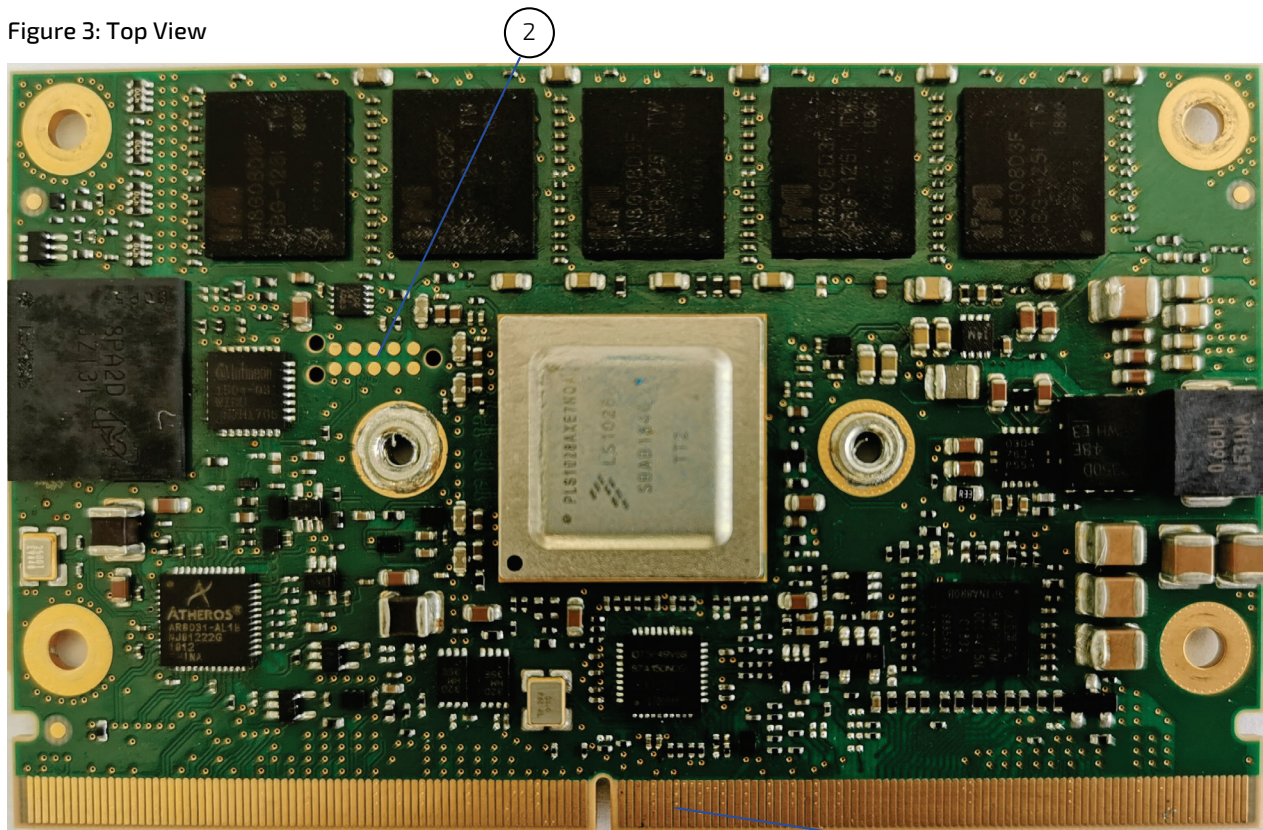
### 4.1.1. Connectors

Table 6: Connectors of SMARC-sAL28

Connector	Function	Remark
SMARC	Central Interface	Mating connector: SMARC 2.0 (MXM3)

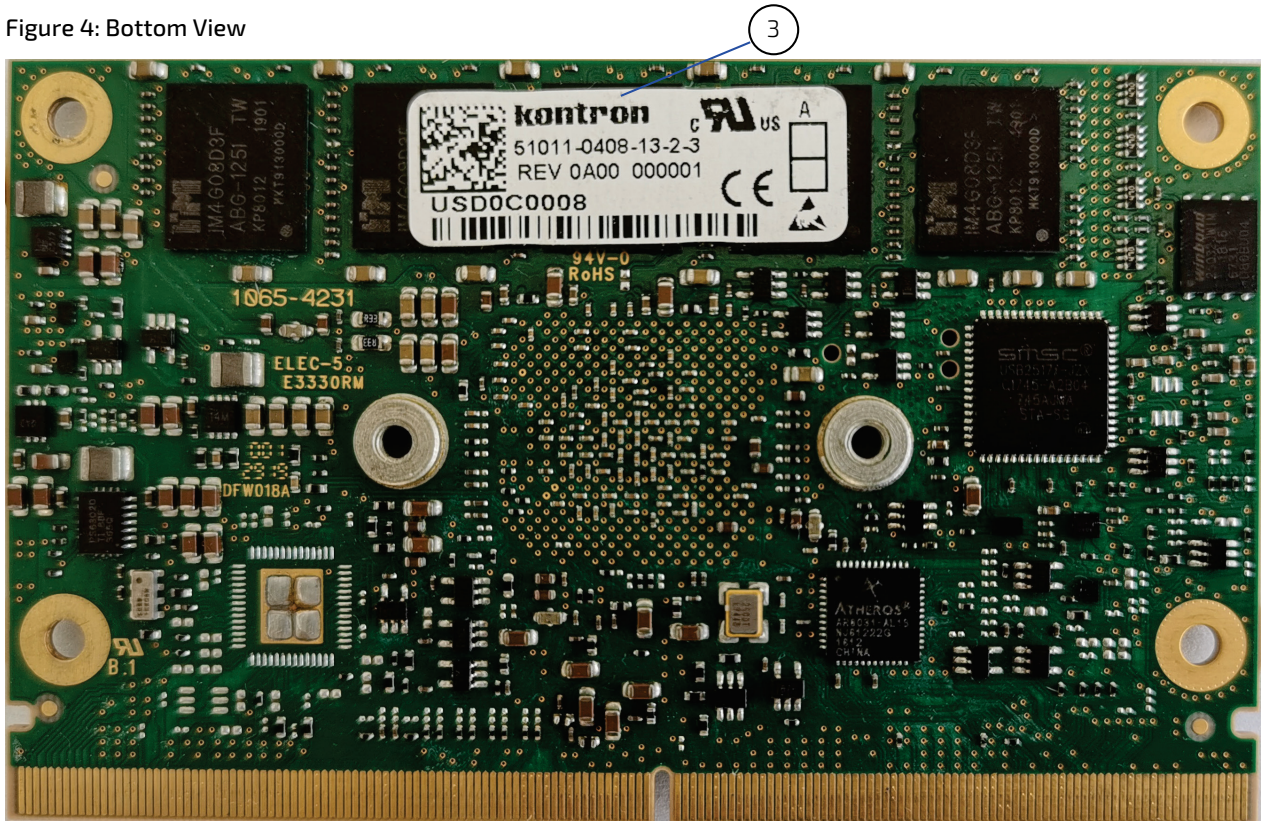
### 4.2. Mainboard view and I/O locations

Figure 3: Top View



1. SMARC 2.0 module connector
2. Debug connector

Figure 4: Bottom View



3. Product label

### 4.3. Mechanical Drawings

Figure 5: Dimensions of SMARC-sAL28

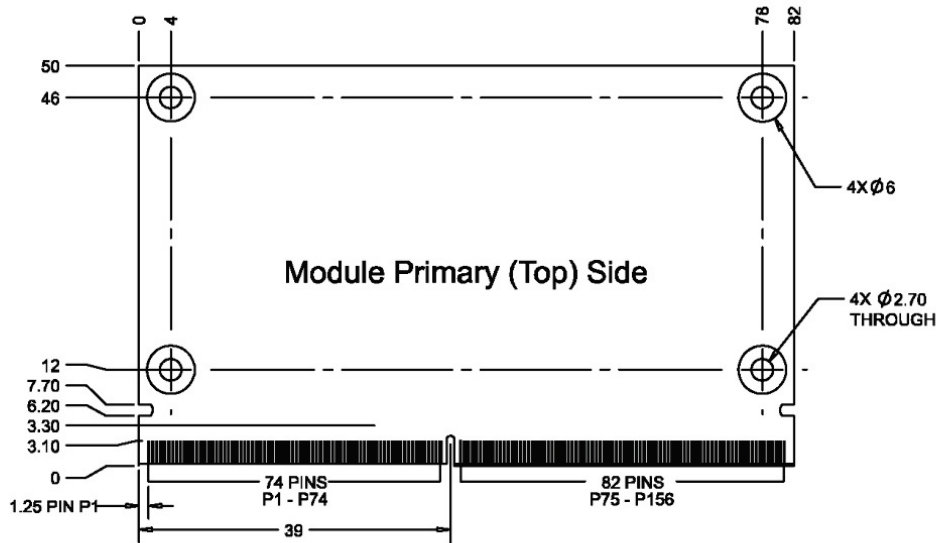
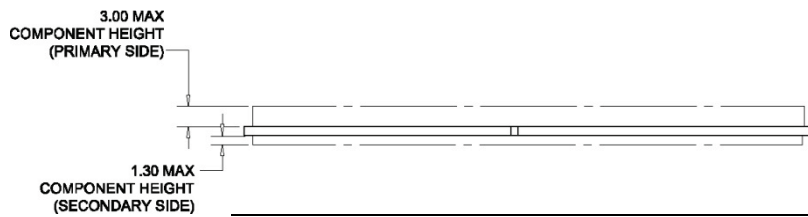


Figure 6: Thickness from side view



**NOTICE**

Heat spreader mech. data is available on customer section

## 5/ Pin Definitions

### 5.1. Processor Support

The Dual Cortex A72-Core LS1028A processor is the base for the SMARC 2.0 Computer-on-Module.

**Table 7: Processor Support**

Name	Speed	RAM.	Cache	TDP/Tj
LS1028A	1.3 GHz	48 KB L1-I, 32 KB L1-D	1 MB L2 Cache	5 W/-40°C to 105°C

### 5.2. System Memory Support

The memory system has DDR3L memory down with ECC support. Memory size up to 8 GB is possible, options for less size also.

The sAL28 design supports two DDR3L banks with 5 DDR3L devices per bank. Bank 1 is assembled on the top side of the PCB and accessible with chip selects CS0#. The second bank is connected with address mirroring, assembled on the bottom side of the PCB and accessible with chip selects CS1#. Default DDR3L Memory sizes are 2 GByte and 4 GByte.

**Table 8: DDR3L memory options**

DDR3L memory size	DDR3L memory configuration
512 MB	5x 1 GBit density 128Mx8 DDR3L parts
1 GByte	5x 2 GBit density 256Mx8 DDR3L parts
2 GByte	5x 4 GBit density 512Mx8 DDR3L parts
4 GByte	10x 4 GBit density 512Mx8 DDR3L parts
8 GByte	10x 8 GBit density 1024Mx8 DDR3L parts

### 5.3. SPI NOR Flash

One SPI NOR flash with package WSON8 6x5mm is connected at XSPI1\_A interface of LS1028A. Up to 128 GBits (16 Mbytes) are available in this package. Following parts are optional possible:

**Table 9: SPI NOR Flash**

SPI NOR Flash size	SPI NOR flash configuration
2 Mbytes	16 MBit serial flash memory with dual SPI
4 Mbytes	32 MBit serial flash memory with dual SPI
8 Mbytes	64 MBit serial flash memory with dual SPI
16 Mbytes	128 MBit serial flash memory with dual SPI

Default SPI NOR flash part is 4 Mbytes.



## 5.4. I2C Buses

Four I2C buses are available at the SMARC-sAL28 module.

**Table 10: I2C Buses**

SMARC Connector	I2C Bus	LS1028A	Devices with I2C address
-/-	I2C_LOCAL	IIC1	DP to LVDS converter PTN3460I (0x20) USB HUB USB2517, (0x2c resistor option) RTC RV8803 (0x32) CPLD (0x4a) RCW EEPROM AT24C32 (0x50)
I2C_PM	I2C_PM	IIC4 <sup>1</sup>	No devices at module connected
I2C_GP	I2C_GP	IIC5	Module EEPROM AT24C32 (0x50)
I2C_LCD	I2C_LCD <sup>2</sup>	-/-	No devices at module connected

<sup>1</sup> Shares second CAN bus, therefore options to short PM bus with I2C local or I2C GP bus are available

<sup>2</sup> The I2C bus for LCD display (I2C\_LCD\_SDA, I2C\_LCD\_SCL) derived from the DP-to-LVDS display converter and is only available with the LVDS display converter option

The SMB\_ALERT\_1V8# signal derives from CPLD (register 0x1C, bit 1).

## 5.5. SPI Interfaces

Two SPI buses are available at the SMARC-sAL28 module.

**Table 11: SPI Buses**

SMARC Connector	LS1028A
SPIO	SPI3
ESPI	XSPI1_A

SPIO in standard option has one chip select (SPIO\_CS0#). Optional the second chip (SPIO\_CS1#) select is possible with abandonment of USB3 power control from CPU.

ESPI in standard option has SPI flash on board at the first chip select. The second chip select is available at the SMARC connector (ESPI\_CS1#). Optional, the first chip select (ESPI\_CS0#) is reconfigurable from SPI flash to the SMARC connector.

The ESPI signals ESPI\_ALERT0#, ESPI\_ALERT1# and ESPI\_RESET# derive from CPLD:

ESPI\_ALERT0#: CPLD register 0x1C, bit 2

ESPI\_ALERT1#: CPLD register 0x1C, bit 3

## 5.6. eMMC NAND Flash Memory

The SDHC2 interface of the LS1028A is connected to the eMMC.

Specific eMMC Flash memory features are:

- ▶ Up to 64 GByte pSLC (or 128 GB MLC)
- ▶ eMMC 5.1 specification
- ▶ Class 0 (basic); class 2 (block read); class 4 (block write); class 5 (erase); class 6 (write protection); class 7 (lock card)
- ▶ HS200 modes
- ▶ DDR modes up to 52 MHz clock speed
- ▶ ECC and block management

- ▶ Boot operation (High-speed boot)
- ▶ Sleep mode
- ▶ Permanent and power-on write protection
- ▶ Replay-protected memory block (RPMB)
- ▶ Secure erase and secure trim

**Table 12: eMMC NAND Flash**

eMMC NAND Flash	Product Number
8 MBytes pSLC	MTFC16GAPALBH-IT
16 MBytes pSLC	MTFC32GAPALBH-IT
32 MBytes pSLC	MTFC64GAPALBH-IT
64 MBytes pSLC	MTFC128GAPALNS-IT

Pure SLC devices are not available anymore with eMMC technology. The eMMC is reconfigured to pseudo SLC (pSLC) at the standard products. Maximum possible eMMC size with pSLC is 64 Mbytes.

## 5.7. SD-Card Interface

The SDHC1 interface of the LS1028A is connected to the SD-card interface at the Smarc 2.0 connector.

**Table 13: SD-Card Interface**

SDIO/SDHC Bus	LS1028A	SMARC Connector
SDIO_D0	SDHC1_DAT0	SDIO_D0
SDIO_D1	SDHC1_DAT1	SDIO_D1
SDIO_D2	SDHC1_DAT2	SDIO_D2
SDIO_D3	SDHC1_DAT3	SDIO_D3
SDIO_CK	SDHC1_CLK	SDIO_CK
SDIO_CD#	SDHC1_CD#	SDIO_CD#
SDIO_CMD	SDHC1_CMD	SDIO_CMD
SDIO_WP	SDHC1_WP	SDIO_WP
-/-	SDHC1_VSEL <sup>3</sup>	-/-
SDIO_PWR_EN	-/- <sup>4</sup>	SDIO_PWR_EN

<sup>3</sup> Selects between 3.3 V and 1.8 V IO voltage with FET switcher

<sup>4</sup> Controlled from CPLD

## 5.8. SerDes Interfaces

The SerDes Interface in the LS1028A has four lanes. The PCIe and Ethernet interfaces are connected to these four lanes with some restrictions.

The four predefined PCIe SMARC Lane-A to Lane-D are mapped to the SerDes Lanes of the LS1028A in a special order.

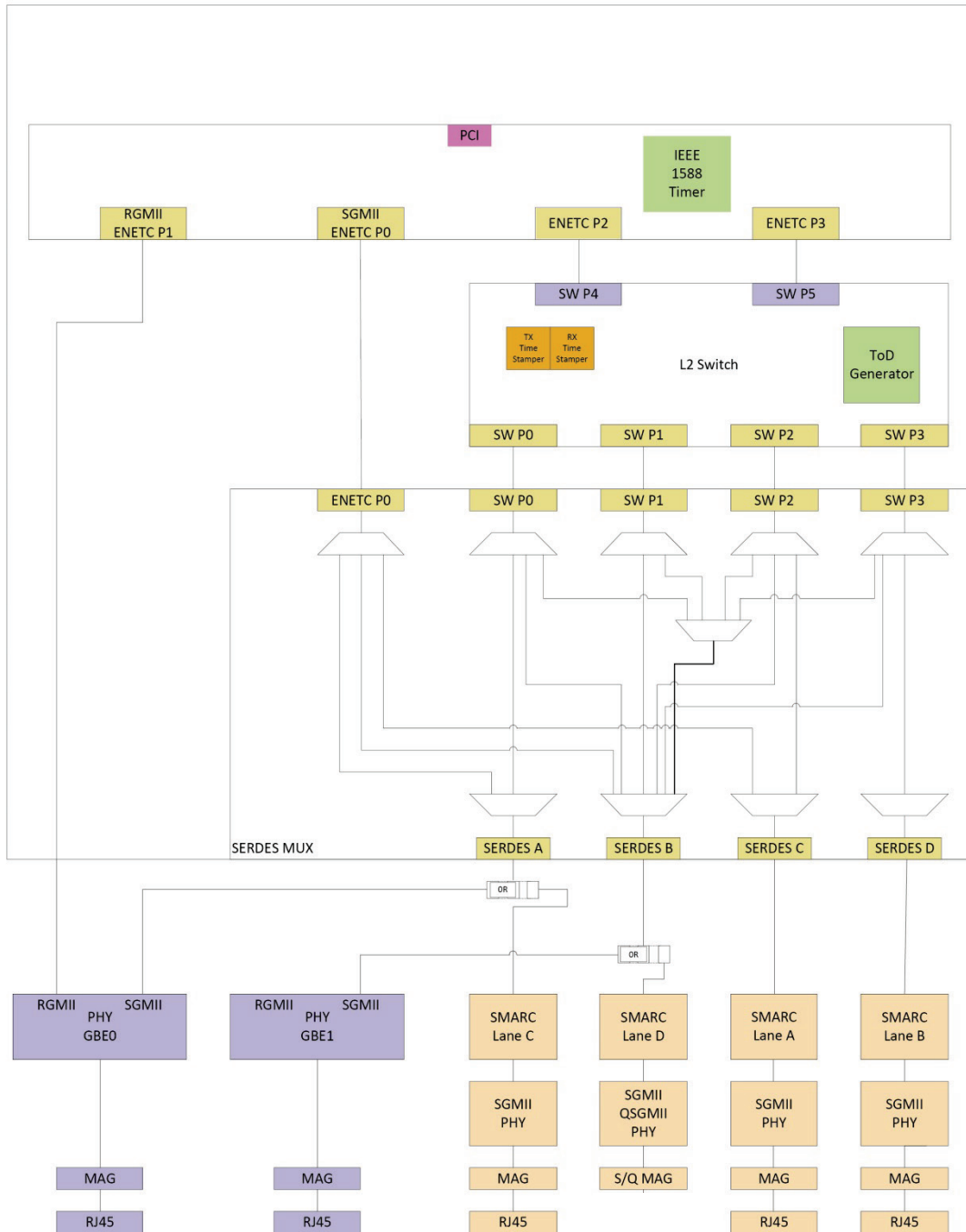
**Table 14: SerDes Interfaces**

SMARC Connector	LS1028A	Option
PCIE_A	SD1_TX2/SD1_RX2 (LANE2)	-/-
PCIE_B	SD1_TX3/SD1_RX3 (LANE3)	-/-
PCIE_C	SD1_TX0/SD1_RX0 (LANE0)	SGMII_LO (GBE0)
PCIE_D	SD1_TX1/SD1_RX1 (LANE1)	SGMII_L1 (GBE1)

There are maximum 2 PCIe controller and following combinations possible:

- ▶ 2x PCIe x1 (PCIe x1: PCIE\_A and PCIe x1: PCIE\_B)
- ▶ 1x PCIe x1 + 1x SATA (PCIe x1: PCIE\_A and SATA: PCIE\_B)
- ▶ 1x PCIe x2 + 1x PCIe x1 (PCIe x2: PCIE\_A + PCIE\_B x2 and PCIe x1: PCIE\_C)
- ▶ 2x PCIe x2 (PCIe x2: PCIE\_A + PCIE\_B and PCIe x2: PCIE\_C + PCIE\_D)
- ▶ 1x PCIe x4, possible with custom carrier, because special lane order (CDAB instead of ABCD)

Figure 7: SerDes Interface Matrix in LS1028A with SMARC PCIe Lanes Connections



## 5.9. CAN Interfaces

There is one CAN interface available with standard boards. A second CAN interface is available if I2C\_PM is disabled or shared with I2C\_GP or I2C\_LOCAL.

**Table 15: CAN Interfaces**

SMARC Connector	LS1028A	Option
CAN0	CAN1	Available on all standard boards
CAN1	CAN2	At custom module with restriction for I2C_GP

## 5.10. USB Interfaces

Six USB 2.0 interfaces are available at the SMARC-sAL28 module. The USB port 3 has also USB 3.1 GEN1 capabilities.

The USB OTG feature is available on port 3, USB port 0 has no OTG feature.

**Table 16: USB Interfaces**

SMARC Connector	LS1028A	USB HUB USB2517I	Comment
USB0	-/-	USB HUB port 1	No OTG feature
USB1	-/-	USB HUB port 2	
USB2	-/-	USB HUB port 3	
USB3	USB1	-/-	With OTG feature with USB 3.1 GEN1 capabilities
USB4	-/-	USB HUB port 4	
USB5	-/-	USB HUB port 5	

### 5.10.1. USB OTG Port

LS1028A USB1 port is used for SMARC USB3 OTG port because this is the only SMARC port which can supports both: OTG and USB 3.1 GEN1.

## 5.11. UART Interfaces

Three UART interfaces are available at the SMARC-sAL28 module.

**Table 17: UART Interfaces**

SMARC Connector	LS1028A	Comment
SER0	LPUART2	With flow control capabilities (RTS/CTS signals)
SER1	UART1	Standard serial console for u-boot access No flow control capabilities
SER2	UART2	No flow control capabilities
SER3	-/-	Not connected on SMARC-sAL28

## 5.12. Ethernet Interfaces

Depending on the network configuration, up to two native 1000BaseT Ethernet with AR8031 PHYs (GBE0 and GBE1) are available.

Additional network ports (connected to CPU internal switch) are possible with an external quad port PHY (QSGMII) at the carrier.

There are four possible network variants

**Table 18: Network variants**

Variant	GBE0	GBE1	Comment
1	RGMII	-/-	Available on customer request no audio support all PCIe combination possible QSGMII on PCIE_D
2	SGMII Lane 0	SGMII LANE 1	Audio support PCIe on PCIE_A and PCIE_B no QSGMII on PCIE_D
3	SGMII Lane 0	-/-	Audio support PCIe on PCIE_A and PCIE_B QSGMII on PCIE_D
4	SGMII Lane 0	RGMII	No audio support PCIe on PCIE_A and PCIE_B QSGMII on PCIE_D

### 5.12.1. GBE0

The GBE0 PHY is available on each network variant.

Network variant 1 has the PHY to CPU connection with RGMII and MDIO address 0x4 (0b00100).

Network variants 2, 3 and 4 has the PHY to CPU connection with SGMII Lane 0 and MDIO address 0x5 (0b00101).

### 5.12.2. GBE1

The GBE1 PHY is available on network variant 2 and 4. Their PHY address in all cases is 0x4 (0b00100).

### 5.12.3. MDIO

There is one MDIO bus for all PHYs - on module PHYs and on carrier PHYs.

PHY addresses on module are 0x4 (0b00100) and 0x5 (0b00101) and cannot be used on carrier.

**Table 19: MDIO Interfaces**

SMARC Connector	LS1028A	Comment
MDIO	EMI1_MDIO	2k21 pull-up to 1.8V on module
MDC	EMI1_MDC	Decoupled with 1.8V 74LVD1G17 Schmitt trigger buffer

### 5.12.4. QSGMII

On network variant 1, 3 and 4 there is one QSGMII interface available at SMARC 2.0 connector port PCIE\_D.

With a suitable carrier (e.g. KBOX A-230-LS) this interface allows 4 additional 1000Base-T network ports. These ports connects the CPU with the CPU internal TSN capable switch.

### 5.13. Audio Interfaces

Up to one I2C audio interface is available at the SMARC-sAL28 module.

The network variants 2 and 3 can support the audio feature.

**Table 20: Audio Interface**

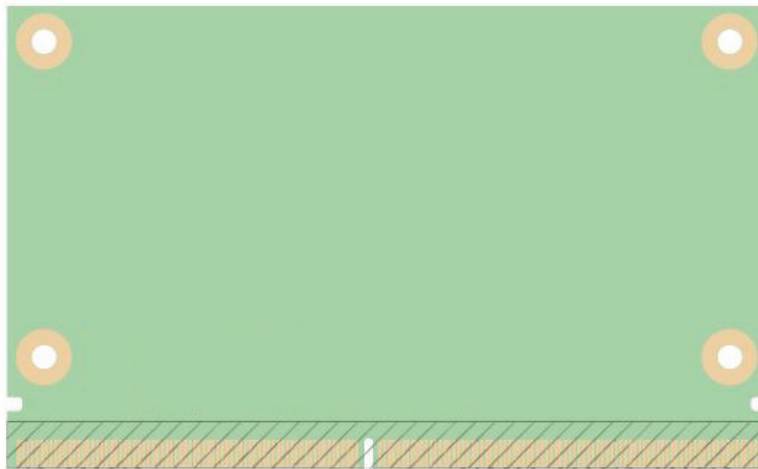
SMARC Connector	LS1028A	Comment
AUDIO_MCK	FTM1_CH2	Whole-numbered divider frequencies of 400MHz possible Default is 1.25MHz
I250_CK	SAI5_RX_BCLK SAI6_TX_BCLK	
I250_LRCK	SAI5_RX_SYNC SAI6_TX_SYNC	
I250_SDIO	SAI5_RX_DATA	
I250_SDOUT	SAI6_TX_DATA	

### 5.14. SMARC Connector

The SMARC connector has different pins on both sides:

- ▶ Top side: 74 pins are on the left side, 82 pins on the right side
- ▶ Bottom side: 75 pins are on the left side, 83 pins on the right side

**Figure 8: 314-pin SMARC Connector,**



## 5.15. Pinout of SMARC sAL28 Connector

### 5.15.1. Pinout of SMARC sAL28 Topside Connector

Table 21: Pinout of SMARC sAL28 Topside Connector

Pin	Signal	Module Direction	Module Termination	Type/Tolerance	Connected Device	Device pin name
P1	SMB_ALERT_1V8#	In	PU-475k	CMOS 1.8V	CPLD	IO_A6
P2	GND	-	-	GND	GND	GND
P3	CSI1_CK+	In	-	LVDS D-PHY	-	-
P4	CSI1_CK-	In	-	LVDS D-PHY	-	-
P5	GBE1_SDP	Bi-Dir	PU-10k	CMOS 3.3V	AR8031/LS1028A	PPS/ SWITCH_1588_DAT1
P6	GBE0_SDP	Bi-Dir	PU-10k	CMOS 3.3V	AR8031/LS1028A	PPS/ SWITCH_1588_DAT0
P7	CSI1_D0+	In	-	LVDS D-PHY	-	-
P8	CSI1_D0-	In	-	LVDS D-PHY	-	-
P9	GND	-	-	GND	GND	GND
P10	CSI1_D1+	In	-	LVDS D-PHY	-	-
P11	CSI1_D1-	In	-	LVDS D-PHY	-	-
P12	GND	-	-	GND	GND	GND
P13	CSI1_D2+	In	-	LVDS D-PHY	-	-
P14	CSI1_D2-	In	-	LVDS D-PHY	-	-
P15	GND	-	-	GND	GND	GND
P16	CSI1_D3+	IN	-	LVDS D-PHY	-	-
P17	CSI1_D3-	IN	-	LVDS D-PHY	-	-
P18	GND	-	-	GND	GND	GND
P19	GBE0_MDI3-	Bi-Dir	-	GBE MDI	AR8031	TRX3-
P20	GBE0_MDI3+	Bi-Dir	-	GBE MDI	AR8031	TRX3+
P21	GBE0_LINK100#	Out/ OD	-	CMOS 3.3V	AR8031	LED_LINK10_100
P22	GBE0_LINK1000#	Out/ OD	-	CMOS 3.3V	AR8031	LED_LINK1000
P23	GBE0_MDI2-	Bi-Dir	-	GBE MDI	AR8031	TRX2-
P24	GBE0_MDI2+	Bi-Dir	-	GBE MDI	AR8031	TRX2+
P25	GBE0_LINK_ACT#	Out/ OD	-	CMOS 3.3V	AR8031	LED_ACT
P26	GBE0_MDI1-	Bi-Dir	-	GBE MDI	AR8031	TRX1-
P27	GBE0_MDI1+	Bi-Dir	-	GBE MDI	AR8031	TRX1+
P28	GBE0_CTREF	Out	-	-	-	-
P29	GBE0_MDIO-	Bi-Dir	-	GBE MDI	AR8031	TRX0-
P30	GBE0_MDIO+	Bi-Dir	-	GBE MDI	AR8031	TRX0+
P31	SPIO_CS1#	Out	PU-10k	CMOS 1.8V	LS1028A	SPI3_PCS2
P32	GND	-	-	GND	GND	GND
P33	SDIO_WP	In	PU-10k	CMOS 3.3V	LS1028A	SDHC1_WP
P34	SDIO_CMD	Bi-Dir	PU-10k	CMOS 3.3V/1.8V	LS1028A	SDHC1_CMD
P35	SDIO_CD#	In	PU-10k	CMOS 3.3V	LS1028A	SDHC1_CD_B
P36	SDIO_CK	Out	Serial-OR	CMOS 3.3V/1.8V	LS1028A	SDHC1_CLK
P37	SDIO_PWR_EN	Out	PU-1k	CMOS 3.3V	CPLD	IO_K7
P38	GND	-	-	GND	GND	GND
P39	SDIO_D0	Bi-Dir	-	CMOS 3.3V/1.8V	LS1028A	SDHC1_DAT0
P40	SDIO_D1	Bi-Dir	-	CMOS 3.3V/1.8V	LS1028A	SDHC1_DAT1



Pin	Signal	Module Direction	Module Termination	Type/Tolerance	Connected Device	Device pin name
P41	SDIO_D2	Bi-Dir	-	CMOS 3.3V/1.8V	LS1028A	SDHC1_DAT2
P42	SDIO_D3	Bi-Dir	-	CMOS 3.3V/1.8V	LS1028A	SDHC1_DAT3
P43	SPI0_CS0#	Out	PU-4k75	CMOS 1.8V	LS1028A	SPI3_PC50
P44	SPI0_CK	Out	-	CMOS 1.8V	LS1028A	SPI3_SCK
P45	SPI0_DIN	In	-	CMOS 1.8V	LS1028A	SPI3_SIN
P46	SPI0_DO	Out	-	CMOS 1.8V	LS1028A	SPI3_SOUT
P47	GND	-	-	GND	GND	GND
P48	SATA_TX+	Out	-	SATA	-	-
P49	SATA_TX-	Out	-	SATA	-	-
P50	GND	-	-	GND	GND	GND
P51	SATA_RX+	In	-	SATA	-	-
P52	SATA_RX-	In	-	SATA	-	-
P53	GND	-	-	GND	GND	GND
P54	ESPI_CS0#	Out	PU-10k	CMOS 1.8V	LS1028A option	XSPI1_A_CS0_B
P55	ESPI_CS1#	Out	PU-10k	CMOS 1.8V	LS1028A	XSPI1_A_CS1_B
P56	ESPI_CK	Out	Serial-33R2	CMOS 1.8V	LS1028A	XSPI1_A_SCK
P57	ESPI_IO_0	In	-	CMOS 1.8V	LS1028A	XSPI1_A_DATA0
P58	ESPI_IO_1	Out	-	CMOS 1.8V	LS1028A	XSPI1_A_DATA1
P59	GND	-	-	GND	GND	GND
P60	USB0+	Bi-Dir	-	USB	USB hub	USB_DN_D1+
P61	USB0-	Bi-Dir	-	USB	USB hub	USB_DN_D1-
P62	USB0_EN_OC#	Bi-Dir OD	PU-4k75	CMOS 3.3V	USB hub	PRTPW1
P63	USB0_VBUS_DET	In	-	CMOS 3.3V	-	-
P64	USB0_OTG_ID	In	-	CMOS 3.3V	-	-
P65	USB1+	Bi-Dir	-	USB	USB hub	USB_DN_D2+
P66	USB1-	Bi-Dir	-	USB	USB hub	USB_DN_D2-
P67	USB1_EN_OC#	Bi-Dir OD	PU-4k75	CMOS 3.3V	USB hub	PRTPW2 + OCS2
P68	GND	-	-	GND	GND	GND
P69	USB2+	Bi-Dir	-	USB	USB hub	USB_DN_D3+
P70	USB2-	Bi-Dir	-	USB	USB hub	USB_DN_D3-
P71	USB2_EN_OC#	Bi-Dir OD	PU-4k75	CMOS 3.3V	USB hub	PRTPW3 + OCS3
P72	RSVD	-	1.8V	PWR	Tamper Power	-
P73	RSVD	-	-	-	-	-
P74	USB3_EN_OC#	Bi-Dir OD	PU-4k75	CMOS 3.3V	CPLD	IO_G2
P75	PCIE_A_RST#	Out	PU-CPLD	CMOS 3.3V	CPLD	IO_B1
P76	USB4_EN_OC#	Bi-Dir OD	PU-4k75	CMOS 3.3V	USB hub	PRTPW4
P77	RSVD	-	-	-	-	-
P78	RSVD	-	-	-	-	-
P79	GND	-	-	GND	GND	GND
P80	PCIE_C_REFCK+	Out	Serial-33R2	LVDS PCIe	5P49V6967	OUT7+
P81	PCIE_C_REFCK-	Out	Serial-33R2	LVDS PCIe	5P49V6967	OUT7-
P82	GND	-	-	GND	GND	GND

Pin	Signal	Module Direction	Module Termination	Type/Tolerance	Connected Device	Device pin name
P83	PCIE_A_REFCK+	Out	Serial-33R2	LVDS PCIe	5P49V6967	OUT5+
P84	PCIE_A_REFCK-	Out	Serial-33R2	LVDS PCIe	5P49V6967	OUT5-
P85	GND	-	-	GND	GND	GND
P86	PCIE_A_RX+	In	-	LVDS PCIe	LS1028A	SD1_RX2_P
P87	PCIE_A_RX-	In	-	LVDS PCIe	LS1028A	SD1_RX2_N
P88	GND	-	-	GND	GND	GND
P89	PCIE_A_TX+	Out	Serial-220n	LVDS PCIe	LS1028A	SD1_TX2_P
P90	PCIE_A_TX-	Out	Serial-220n	LVDS PCIe	LS1028A	SD1_TX2_N
P91	GND	-	-	GND	GND	GND
P92	HDMI_D2+/ DP1_LANE0+	Out	-	TMDS	-	-
P93	HDMI_D2-/ DP1_LANE0-	Out	-	TMDS	-	-
P94	GND	-	-	GND	GND	GND
P95	HDMI_D1+ / DP1_LANE1+	Out	-	TMDS	-	-
P96	HDMI_D1-/ DP1_LANE1-	Out	-	TMDS	-	-
P97	GND	-	-	GND	GND	GND
P98	HDMI_D0+/ DP1_LANE2+	Out	-	TMDS	-	-
P99	HDMI_D0-/ DP1_LANE2-	Out	-	TMDS	-	-
P100	GND	-	-	GND	GND	GND
P101	HDMI_CK+ / DP1_LANE3+	Out	-	TMDS	-	-
P102	HDMI_CK-/ DP1_LANE3-	Out	-	TMDS	-	-
P103	GND	-	-	GND	GND	GND
P104	HDMI_HPD/ DP1_HPD	In	-	CMOS 1.8V	-	-
P105	HDMI_CTRL_CK/ DP1_AUX+	Out	-	CMOS 1.8V	-	-
P106	HDMI_CTRL_DAT/ DPS1_AUX-	Bi-Dir	-	CMOS 1.8V	-	-
P107	DP1_AUX_SEL	In	-	CMOS 1.8V	-	-
P108	GPIO0/ CAM0_PWR#	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_J11
P109	GPIO1/ CAM1_PWR#	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_H11
P110	GPIO2/ CAM0_RST#	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_F11
P111	GPIO3/ CAM1_RST#	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_E11
P112	GPIO4/ HDA_RST#	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_D11
P113	GPIO5/ PWM_OUT	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_C11
P114	GPIO6/ TACHIN	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_B11
P115	GPIO7	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_A11
P116	GPIO8	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_A10
P117	GPIO9	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_A9
P118	GPIO10	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_A8

Pin	Signal	Module Direction	Module Termination	Type/Tolerance	Connected Device	Device pin name
P119	GPIO11	Bi-Dir	PU-475k	CMOS 1.8V	CPLD	IO_K11
P120	GND	-	-	GND	GND	GND
P121	I2C_PM_CK	Bi-Dir	PU-2k2	CMOS 1.8V	LS1028A	IIC1_SCL
P122	I2C_PM_DAT	Bi-Dir	PU-2k2	CMOS 1.8V	LS1028A	IIC1_SDA
P123	BOOT_SEL0#	In	PU-CPLD	CMOS 1.8V	CPLD	IO_J10
P124	BOOT_SEL1#	In	PU-CPLD	CMOS 1.8V	CPLD	IO_H10
P125	BOOT_SEL2#	In	PU-CPLD	CMOS 1.8V	CPLD	IO_H9
P126	RESET_OUT#	Out -OD	Serial-825R PD-1k	CMOS 1.8V	CPLD	IO_L2
P127	RESET_IN#	In	PU-10k	CMOS 1.8V	LS1028A	PORESET_B
P128	POWER_BTN#	In	PU-CPLD	CMOS 1.8V	CPLD	IO_G10
P129	SER0_TX	Out	-	CMOS 1.8V	LS1028A	LPUART2_SOUT
P130	SER0_RX	In	-	CMOS 1.8V	LS1028A	LPUART2_SIN
P131	SER0_RTS#	Out	-	CMOS 1.8V	LS1028A	LPUART2_CTS_B
P132	SER0_CTS#	In	-	CMOS 1.8V	LS1028A	LPUART2_RTS_B
P133	GND	-	-	GND	GND	GND
P134	SER1_TX	Out	-	CMOS 1.8V	LS1028A	UART1_SOUT
P135	SER1_RX	In	-	CMOS 1.8V	LS1028A	UART1_SIN
P136	SER2_TX	Out	-	CMOS 1.8V	LS1028A	UART2_SOUT
P137	SER2_RX	In	-	CMOS 1.8V	LS1028A	UART2_SIN
P138	SER2_RTS#	Out	-	CMOS 1.8V	-	-
P139	SER2_CTS#	In	-	CMOS 1.8V	-	-
P140	SER3_TX	Out	-	CMOS 1.8V	-	-
P141	SER3_RX	In	-	CMOS 1.8V	-	-
P142	GND	-	-	GND	GND	GND
P143	CAN0_TX	Out	-	CMOS 1.8V	LS1028A	CAN1_TX
P144	CAN0_RX	In	-	CMOS 1.8V	LS1028A	CAN1_RX
P145	CAN1_TX	Out	-	CMOS 1.8V	LS1028A option	IIC4_SCL
P146	CAN1_RX	In	-	CMOS 1.8V	LS1028A option	IIC4_SDA
P147	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P148	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P149	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P150	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P151	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P152	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P153	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P154	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P155	VDD_IN	PWR	-	3.0V - 5.25V	Power	-
P156	VDD_IN	PWR	-	3.0V - 5.25V	Power	-

## 5.15.2. Pinout of SMARC sAL28 Bottom Side Connector

Table 22: Pinout of SMARC sAL28 Bottom Side Connector

Pin	Signal	Module Direction	Module Termination	Type/ Tolerance	Connected Device	Device pin name
S1	CSI1_TX+/ IZC_CAM1_CK	In	-	TMDS/ CMOS 1.8V	-	-
S2	CSI1_TX-/ IZC_CAM1_DAT	In	-	TMDS/ CMOS 1.8V	-	-
S3	GND	-	-	GND	GND	GND
S4	RSVD	-	-	CMOS 1.0V	LS1028A	TA_BB_TMP_DETECT#
S5	CSI0_TX+/ IZC_CAM0_CK	Out	-	CMOS 1.8V -	-	-
S6	CAM_MCK	Out	-	CMOS 1.8V	-	-
S7	CSI0_TX-/ IZC_CAM0_DAT	Bi-Dir	-	CMOS 1.8V	-	-
S8	CSI0_CK+	In	-	LVDS D-PHY	-	-
S9	CSI0_CK-	In	-	LVDS D-PHY	-	-
S10	GND	-	-	GND	GND	GND
S11	CSI0_RX0+	In	-	LVDS D-PHY	-	-
S12	CSI0_RX0-	In	-	LVDS D-PHY	-	-
S13	GND	-	-	GND	GND	GND
S14	CSI0_RX1+	In	-	LVDS D-PHY	-	-
S15	CSI0_RX1-	In	-	LVDS D-PHY	-	-
S16	GND	-	-	GND	GND	GND
S17	GBE1_MDIO+	Bi-Dir	-	GBE MDI	AR8031	TRX0+
S18	GBE1_MDIO-	Bi-Dir	-	GBE MDI	AR8031	TRX0-
S19	GBE1_LINK100#	Out/ OD	-	CMOS 3.3V	AR8031	LED_LINK10_100
S20	GBE1_MDII+	Bi-Dir	-	GBE MDI	AR8031	TRX1+
S21	GBE1_MDII-	Bi-Dir	-	GBE MDI	AR8031	TRX1-
S22	GBE1_LINK1000#	Out/ OD	-	CMOS 3.3V	AR8031	LED_LINK1000
S23	GBE1_MDI2+	Bi-Dir	-	GBE MDI	AR8031	TRX2+
S24	GBE1_MDI2-	Bi-Dir	-	GBE MDI	AR8031	TRX2-
S25	GND	Bi-Dir	-	GND	GND	GND
S26	GBE1_MDI3+	Out	-	GBE MDI	AR8031	TRX3+
S27	GBE1_MDI3-	Bi-Dir	-	GBE MDI	AR8031	TRX3-
S28	GBE1_CTREF	Bi-Dir	-	GBE MDI	-	-
S29	PCIE_D_TX+	Bi-Dir	Serial-220n	LVDS PCIe	LS1028A	SD1_TX0+
S30	PCIE_D_TX-	Bi-Dir	Serial-220n	LVDS PCIe	LS1028A	SD1_TX0-
S31	GBE1_LINK_ACT#	Out/ OD	-	CMOS 3.3V	AR8031	LED_ACT
S32	PCIE_D_RX+	Bi-Dir	Serial-0R	LVDS PCIe	LS1028A	SD1_RX0+
S33	PCIE_D_RX-	Bi-Dir	Serial-0R	LVDS PCIe	LS1028A	SD1_RX0-
S34	GND	-	-	GND	GND	GND
S35	USB4+	Bi-Dir	-	USB	USB hub	USB_DN_D4+
S36	USB4-	Bi-Dir	-	USB	USB hub	USB_DN_D4-
S37	USB3_VBUS_DET	In	-	CMOS 3.3V	LS1028A	USB1_VBUS
S38	AUDIO_MCK	Out	Serial-240R	CMOS 1.8V	LS1028A option	FTM1_CH3

Pin	Signal	Module Direction	Module Termination	Type/Tolerance	Connected Device	Device pin name
S39	I2S0_LRCK	Bi-Dir	Serial-0R	CMOS 1.8V	LS1028A option	SAI4_TX_SYNC
S40	I2S0_SDOOUT	Out	Serial-0R	CMOS 1.8V	LS1028A option	SAI4_TX_DATA
S41	I2S0_SDIN	In	Serial-oR	CMOS 1.8V	LS1028A option	SAI4_TX_DATA
S42	I2S0_CK	Bi-Dir	Serial-0R	CMOS 1.8V	LS1028A option	SAI4_TX_BCLK
S43	ESPI_ALERT0#	In	PU-CPLD	CMOS 1.8V	CPLD	IO_C6
S44	ESPI_ALERT1#	In	PU-CPLD	CMOS 1.8V	CPLD	IO_B6
S45	MDC	OUT	-	CMOS 1.8V	LS1028A option	EMI1_MDC
S46	MDIO	Bi-Dir	PU-2k21	CMOS 1.8V	LS1028A option	EMI1_MDIO
S47	GND	-	-	GND	GND	GND
S48	I2C_GP_CK	Out	PU-2k21	CMOS 1.8V	LS1028A	IIC5_SCL
S49	I2C_GP_DAT	Bi-Dir	PU-2k21	CMOS 1.8V	LS1028A	IIC5_SDA
S50	HDSA_SYNC/ I2S2_LRCK	Bi-Dir	-	CMOS 1.5V/ 1.8V	-	-
S51	HDA_SDO/ I2S2_SDOOUT	Out	-	CMOS 1.5V/ 1.8V	-	-
S52	HDA_SDI/ I2S2_SDIN	In	-	CMOS 1.5V/ 1.8V	-	-
S53	HDA_CK/ I2S2_CK	Bi-Dir	-	CMOS 1.5V/ 1.8V	-	-
S54	SATA_ACT#	-	-	CMOS 3.3V	-	-
S55	USB5_EN_OC#	Bi-Dir OD	PU-10k	CMOS 3.3V	USB hub	PRTPW5 + OC55#
S56	ESPI_IO_2	Bi-Dir	-	CMOS 1.8V	LS1028A	XSPI1_A_DATA2
S57	ESPI_IO_3	Bi-Dir	-	CMOS 1.8V	LS1028A	XSPI1_A_DATA3
S58	ESPI_RESET#	Out	-	CMOS 1.8V	CPLD	IO_L5
S59	USB5+	Bi-Dir	-	USB	USB hub	USB_DN_D5+
S60	USB5-	Bi-Dir	-	USB	USB hub	USB_DN_D5-
S61	GND	-	-	GND	GND	GND
S62	USB3_SSTX+	Bi-Dir	Serial-100n	LVDS_AFB	LS1028A	USB1_TX_P
S63	USB3_SSTX-	Bi-Dir	Serial-100n	LVDS_AFB	LS1028A	USB1_TX_M
S64	GND	-	-	GND	GND	GND
S65	USB3_SSRX+	Bi-Dir	-	LVDS_AFB	LS1028A	USB1_RX_P
S66	USB3_SSRX-	Bi-Dir	-	LVDS_AFB	LS1028A	USB1_RX_M
S67	GND	-	-	GND	GND	GND
S68	USB3+	Bi-Dir	-	LVDS_AFB	LS1028A	USB1_D_P
S69	USB3-	Bi-Dir	-	LVDS_AFB	LS1028A	USB1_D_M
S70	GND	-	-	GND	GND	GND
S71	USB2_SSTX+	Bi-Dir	-	LVDS_AFB	-	-
S72	USB2_SSTX-	Bi-Dir	-	LVDS_AFB	-	-
S73	GND	-	-	GND	GND	GND
S74	USB2_SSRX+	Bi-Dir	-	LVDS_AFB	-	-
S75	USB2_SSRX-	Bi-Dir	-	LVDS_AFB	-	-
S76	PCIE_B_RST#	Out	PU-CPLD	CMOS 3.3V	CPLD	IO_K8
S77	PCIE_C_RST#	Out	PU-CPLD	CMOS 3.3V	CPLD	IO_L9
S78	PCIE_C_RX+	In	Serial-0R	LVDS PCIe	LS1028A option	SD1_RX1_P
S79	PCIE_C_RX-	In	Serial-0R	LVDS PCIe	LS1028A option	SD1_RX1_N
S80	GND	-	-	GND	GND	GND
S81	PCIE_C_TX+	Out	Serial-220n	LVDS PCIe	LS1028A option	SD1_RX1_P

Pin	Signal	Module Direction	Module Termination	Type/Tolerance	Connected Device	Device pin name
S82	PCIE_C_TX-	Out	Serial-220n	LVDS PCIe	LS1028A option	SD1_RX1_N
S83	GND	-	-	GND	GND	GND
S84	PCIE_B_REFCK+	Out	Serial-33R2	LVDS PCIe	5P49V6967	OUT6+
S85	PCIE_B_REFCK-	Out	Serial-33R2	LVDS PCIe	5P49V6967	OUT6-
S86	GND	-	-	GND	GND	GND
S87	PCIE_B_RX+	In	-	LVDS PCIe	LS1028A	SD1_RX3_P
S88	PCIE_B_RX-	In	-	LVDS PCIe	LS1028A	SD1_RX3_N
S89	GND	-	-	GND	GND	GND
S90	PCIE_B_TX+	Out	Serial-220n	LVDS PCIe	LS1028A	SD1_TX3_P
S91	PCIE_B_TX-	Out	Serial-220n	LVDS PCIe	LS1028A	SD1_TX3_N
S92	GND	-	-	GND	GND	GND
S93	DPO_LANE0+	Out	-	LVDS LCD	-	-
S94	DPO_LANE0-	Out	-	LVDS LCD	-	-
S95	DPO_AUX_SEL	In	-	CMOS 1.8V	-	-
S96	DPO_LANE1+	Out	-	LVDS LCD	-	-
S97	DPO_LANE1-	Out	-	LVDS LCD	-	-
S98	DPO_HPDP	In	-	CMOS 1.8V	-	-
S99	DPO_LANE2+	Out	-	LVDS LCD	-	-
S100	DPO_LANE2-	Out	-	LVDS LCD	-	-
S101	GND	-	-	GND	GND	GND
S102	DPO_LANE3+	Out	-	LVDS LCD	-	-
S103	DPO_LANE3-	Out	-	LVDS LCD	-	-
S104	USB3_OTG_ID	Out	-	CMOS 3.3V	LS1028A	USB1_ID
S105	DPO_AUX+	Out	-	LVDS LCD	-	-
S106	DPO_AUX-	Out	-	LVDS LCD	-	-
S107	LCD1_BKLT_EN	Out	-	CMOS 1.8V	-	-
S108	LVDS1_CK+/ eDP1_AUX+/ DSI1_CLK+	Out	-	LVDS LCD	PTN3460I	LVSCKE_P
S109	LVDS1_CK-/ eDP1_AUX-/ DSI1_CLK-	Out	-	LVDS LCD	PTN3460I	LVSCKE_N
S110	GND	-	-	GND	GND	GND
S111	LVDS1_0+/ EDP1_TX0+/ DSI1_D0+	Out	-	LVDS LCD	PTN3460I	LVSAE_P
S112	LVDS1_0-/ EDP1_TX0-/ DSI1_D0-	Out	-	LVDS LCD	PTN3460I	LVSAE_N
S113	eDP1_HPDP	Out	-	CMOS 1.8V	-	-
S114	LVDS1_1+/ EDP1_TX1+/ DSI1_D1+	Out	-	LVDS LCD	PTN3460I	LVSBEP
S115	LVDS1_1-/ EDP1_TX1-/ DSI1_D1-	Out	-	LVDS LCD	PTN3460I	LVSBEN
S116	LCD1_VDD_EN	Out	-	CMOS 1.8V	-	-

Pin	Signal	Module Direction	Module Termination	Type/Tolerance	Connected Device	Device pin name
S117	LVDS1_2+/ eDP1_TX2+/ DSI1_D2+	Out	-	LVDS LCD	PTN3460I	LVSCE_P
S118	LVDS1_2-/ eDP1_TX2-/ DSI1_D2-	Out	-	LVDS LCD	PTN3460I	LVSCE_N
S119	GND	-	-	GND	GND	GND
S120	LVDS1_3+/ eDP1_TX3+/ DSI1_D3+	Out	-	LVDS LCD	PTN3460I	LVSDE_P
S121	LVDS1_3-/ eDP1_TX3-/ DSI1_D3-	Out	-	LVDS LCD	PTN3460I	LVSDE_N
S122	LCD1_BKLT_PWM	Out		CMOS 1.8V	-	-
S123	RSVD	Out	-	CMOS 1.8V	LS1028A option	TA_TMP_DETECT#
S124	GND	-	-	GND	GND	GND
S125	LVDS0_0+/ eDPO_TX0+/ DSI0_D0+	Out	Serial-0R	LVDS LCD	PTN3460I/ LS1028A	LVSAO_P/ DP_LANE0+
S126	LVDS0_0-/ eDPO_TX0-/ DSI0_D0-	Out	Serial-0R	LVDS LCD	PTN3460I/ LS1028A	LVSAO_N/ DP_LANE0-
S127	LCDO_BKLT_EN	Out	Serial-825R PD-1k	CMOS 1.8V	PTN3456I/CPLD	BKLTEN/ IO_C1
S128	LVDS0_1+/ eDPO_TX1+/ DSI0_D1+	Out	Serial-0R	LVDS LCD	PTN3460I/ LS1028A	LVSBO_P/ DP_LANE1+
S129	LVDS0_1-/ eDPO_TX1-/ DSI0_D1-	Out	Serial-0R	LVDS LCD	PTN3460I/ LS1028A	LVSBO_N/ DP_LANE1-
S130	GND	-	-	GND	GND	GND
S131	LVDS0_2+/ eDPO_TX2+/ DSI0_D2+	Out	Serial-0R	LVDS LCD	PTN3460I/ LS1028A	LVSCO_P/ DP_LANE2+
S132	LVDS0_2-/ eDPO_TX2-/ DSI0_D2-	Out	Serial-0R	LVDS LCD	PTN3460I/ LS1028A	LVSCO_N/ DP_LANE2-
S133	LCDO_VDD_EN	Out	Serial-825R PD-1k	CMOS 1.8V	PTN3456I/CPLD	PVCCEN/ IO_H1
S134	LVDS0_CK+/ eDPO_AUX+/ DSI0_CLK+	Out	Serial-0R/ Serial-100n PU-100k	LVDS LCD	PTN3460I/ LS1028A	LVSDO_P/ DP_LANE3+
S135	LVDS0_CK-/ eDPO_AUX-/ DSI0_CLK-	Out	Serial-0R/ Serial-100n PD-100k	LVDS LCD	PTN3460I/ LS1028A	LVSDO_N/ DP_LANE3-
S136	GND	-	-	GND	GND	GND
S137	LVDS0_3+/ eDPO_TX3+/ DSI0_D3+	Out	Serial-0R	LVDS LCD	PTN3460I/ LS1028A	LVSCKO_P/ DP_AUX+
S138	LVDS0_3-/ eDPO_TX3-/ DSI0_D3-	Out	Serial-0R	LVDS LCD	PTN3460I/ LS1028A	LVSCKO_N/ DP_AUX-
S139	IZC_LCD_CK	Out	PU-2k21	CMOS 1.8V	PTN3456I	DDC_SCL

Pin	Signal	Module Direction	Module Termination	Type/Tolerance	Connected Device	Device pin name
S140	I2C_LCD_DAT	Bi-Dir	PU-2k21	CMOS 1.8V	PTN3456I	DDC_SDA
S141	LCD0_BKLT_PWM	Out	Serial-825R PD-1k	CMOS 1.8V	PTN3460I/CPLD	PWMO/ IO_L11
S142	RSVD	-	-	0.97V - 1.05V	Tamper Power	-
S143	GND	-	-	GND	GND	GND
S144	EDPO_HPD	-	-	CMOS 1.8V	PTN3460I/LS1028A	HPDRX/ DP_HPD
S145	WDT_TIME_OUT#	Out	-	CMOS 1.8V	CPLD	IO_D10
S146	PCIE_WAKE #	In	PU-4k75	CMOS 3.3V	CPLD	IO_F2
S147	VDD_RTC	-	Serial-1k	PWR	RTC	power
S148	LID#	In	PU-4k75	CMOS 1.8V	CPLD	IO_D9
S149	SLEEP#	In	PU-4k75	CMOS 1.8V	CPLD	IO_B10
S150	VIN_PWR_BAD#	In	PU-10k	CMOS VDDIN	power circuit	-
S151	CHARGING#	In	PU-CPLD	CMOS 1.8V	CPLD	IO_C10
S152	CHARGER_PRSENT#	In	PU-CPLD	CMOS 1.8V	CPLD	IO_F10
S153	CARRIER_STBY#	Out	Serial-825R PD-1k	CMOS 1.8V	CPLD	IO_L6
S154	CARRIER_PWR_ON	Out	-	CMOS 1.8V	power circuit	-
S155	FORCE_RECOV#	In	PU-4k75	CMOS 1.8V	CPLD	IO_B2
S156	BATLOW#	In	PU_CPLD	CMOS 1.8V	CPLD	IO_G11
S157	TEST#	In	PU-10k	CMOS 1.8V	CPLD	IO_B2
S158	GND	-	-	GND	GND	GND

## 5.16. JTAG Debug connector

Table 23: JTAG Debug connector

Pin#	Signal	Description
1	JTAG_TCK	JTAG clock
2	JTAG_TMS	JTAG test mode select
3	PORESET#	Power on reset for LS1028A, low active signal <sup>3</sup>
4	JTAG_TDO	JTAG test data output
5	V_3V3_S0	3.3V supply and I/O level voltage use also for JTAG_EN_3V3
6	JTAG_TDI	JTAG test data input
7	JTAG_EN_3V3	JTAG enable, high active signal
8	I2C_LOCAL_SDA_3V3	I2C_LOCAL bus data signal, I/O level: 3.3V
9	GND	Ground
10	I2C_LOCAL_SCL_3V3	I2C_LOCAL bus clock signal, I/O level: 3.3V

<sup>3</sup> need to be an open drain signal (push/pull with direct connection of CodeWarrior TAP would not work)



## 6/ Configuration

### 6.1. Boot Mode

The following table shows the possible boot sources on the carrier board defined in SMARC 2.0 spec:

Table 24: Boot Options on the carrier board

	Carrier Connection			Boot Source	Supported on sAL28
	BOOT_SEL2#	BOOT_SEL1#	BOOT_SELO#		
0	GND	GND	GND	Carrier SATA	No
1	GND	GND	Float	Carrier SD Card	From U-Boot
2	GND	Float	GND	Carrier eSPI (CS0#)	From U-Boot
3	GND	Float	Float	Carrier SPI (CS0#)	From U-Boot
4	Float	GND	GND	Module device (NAND, NOR)	No
5	Float	GND	Float	Remote boot (GBE, serial)	From U-Boot
6	Float	Float	GND	Module eMMC Flash	From u-boot
7	Float	Float	Float	Module SPI	From u-boot

When the CPLD code is active, the SL1028A boot selection pins are pulled from CPLD to boot from I2C\_LOCAL bus (LS1028A I2C1). The EEPROM at I2C\_LOCAL bus (address 0x50) contains RCW and PBI which selects the XSPI1\_A bus with chip select 0 to boot from the connected SPI NOR flash.

If the CPLD is not active or if the boot process did not work from I2C1 the SL1028A boot selection pins can be pulled to XSPI1\_A bus which is the default failsafe mechanism in CPLD.

Boot from external SPI is possible with resistor option: disconnect SL1028A chip select 0 from SPI flash and connect SL1028A chip select 0 with SMARC connector ESPI\_CS0.

### 6.2. Configurable Watchdog

There are two watchdogs: a CPU internal and CPLD support watchdog.

### 6.3. RTC current consumption

The VDD\_RTC pin at the SMARC 2.0 Connector has the ability to charge a gold cap capacitor on the carrier. The power source of the VDD\_RTC voltage is V\_3V3\_S5 with BAS70 as series protection diode and an additional series resistance of 240 Ohm.

Optionally, the series resistance is replaceable with an additional BAS70 diode to protect a battery circuit on a carrier which has no diode protection (disable gold cap charging capability).

Table 25: Maximum current consumption of RTC

Ambient temperature	Maximum Current in VDD_RTC
-20°C	0.4 $\mu$ A
25°C	0.6 $\mu$ A
85°C	1.8 $\mu$ A

## 6.4. Power Control

### 6.4.1. Power Supply

The SMARC-sAL28 supports a power input from 3.0 to 5.25V. The supply voltage is applied through the VCC pins (VCC) of the module connector. Considered current rating of protective device is part of End-Equipment.



The following parameters should be delivered from the carrier board:

- ▶ Voltage Ripple maximum 100 mV peak to peak 0-20 MHz to 20 ms rise time from input voltage <10% to nominal VCC
- ▶ Max allowed inrush current: connector limit (15 W @ 3,0 V)
- ▶ There are 5x 47u 1210 10 V bulk capacitors too meet the required noise and ripple requirements.

Table 26: Power Supply Specifications

Voltage rail	Required range	Controller	Frequency
V_5V0_IN	3.0V – 5.25V	Input power	-/-
V_3V3_S5	3.15V – 3.45V	Buck-Boost	2.4 MHz PFM
V_1V8_S5	1.71V – 1.89V	LDO	-/-
V_3V3_S0	3.15V – 3.45V	Switch TPS22964	-/-
V_1V8_S0	1.7V – 1.9V	Buck TLV62084A	2 MHz PWM/PFM
V_1V35_S0	1.283V – 1.45V	Buck TLV62084A	2 MHz PWM/PFM
V_1V0_S0	0.97V – 1.03V	Buck TLV62084A	600 kHz PWM
V_1V0_SVDD_S0	0.971V – 1.05V	Buck TLV62084A	2 MHz PWM/PFM
V_0V675_VTT	0.6415V – 0.725V	LDO	-/-

### 6.4.2. Power Button (POWER\_BTN#)

The power button (Pin P128) is available through the module connector described in the pinout list. To start the module via Power Button the PWRBTN# signal must be at least 50 ms ( $50 \text{ ms} \leq t < 4 \text{ s}$ , typical 400 ms) at low level (Power Button Event).



Pressing the power button for at least 4 seconds will turn off power to the module (Power Button Override).



The module starts automatically after power up to the payload state S0. There is one bit in the NVM where this automatism can be changed: with changed bit the module will stay in state S5 until a power up event occurred. This could be one of this events:

- ▶ Power button pressed
- ▶ One of the wake lines WOL\_INT\_GBE#, PCIE\_WAKE# or RTC\_INT# are asserted

### 6.4.3. Power Management Signals

Following management signals are implemented:

- ▶ VIN\_PWR\_BAD#: Power bad indication from Carrier board. The Module power supply will not be enabled while this signal is held low by the Carrier. VIN\_PWR\_BAD# is pulled up on Module. VIN\_PWR\_BAD# is the enable signal for the 3.3V buck-boost converter on the module (first POL converter).

- ▶ CARRIER\_STBY#: The Module will drive CARRIER\_STBY# low by CPLD when the system is in a standby power state.
- ▶ CARRIER\_PWR\_ON: The "last" power good signal in daisy chained POLs configuration controls the CARRIER\_PWR\_ON signal
- ▶ RESET\_OUT#: The same "last" power good signal as used for CARRIER\_PWR\_ON triggers the minimum 100ms delay of the RESET\_OUT# in the CPLD. Therefore the RESET\_OUT# release arrives between 100ms and 200ms after the CARRIER\_PWR\_ON release.

#### 6.4.4. Battery Control Signals

SLEEP#, BATLOW#, LID#, CHARGING# and CHARGER\_PRSENT# are connected to the CPLD and accessible through CPLD GPI register 0x1B:

- ▶ SLEEP#: CPLD register 0x1B bit 2
- ▶ BATLOW#: CPLD register 0x1B bit 3
- ▶ LID#: CPLD register 0x1B bit 4
- ▶ CHARGING#: CPLD register 0x1B bit 5
- ▶ CHARGER\_PRSENT#: CPLD register 0x1B bit 6

#### **NOTICE**

---

If any of the supply voltages drops below the allowed operating level longer than the specified hold-up time, all the supply voltages should be shut down and left OFF for a time long enough to allow the internal board voltages to discharge sufficiently. If the OFF time is not observed, parts of the board or attached peripherals may work incorrectly or even suffer a reduction of MTBF. The minimum OFF time depends on the implemented PSU model and other electrical factors and needs to be measured individually for each case.

---

#### **NOTICE**

---

To protect external power lines of peripheral devices, make sure that the wires have the right diameter to withstand the maximum available current. The enclosure of the peripheral device has to fulfill the fire-protection requirements of IEC/EN62368.

---

## 7/ Installation and Setup Procedures

The Board Support Package (BSP) is based on Yocto 2.5 Sumo and uses layers from Yocto, OpenEmbedded, and FSL Community BSP projects.

BSP makes use of proprietary hardware support packages that are covered by NXP SOFTWARE LICENSE AGREEMENT. This agreement explicitly disallows redistribution of covered objects. Because of that, the BSP provides sources and binaries/images for open-source components. So rootfs images to deploy and boot on board must be built manually. Yocto tools completely automate this process – including downloading and integrating restricted NXP packages. Brief build instructions are included into this document; for complete information please refer to Yocto documentation at <https://www.yoctoproject.org/documentation>.

For reference, BSP archive includes binary kernel and device tree images that have been used for BSP validation. However, for consistency reasons, it is recommended to use kernel and device tree images created by local build.

### 7.1. Building BSP images (rootfs, kernel, device tree)

1. Make sure that your host development system meets the following requirements:  
<https://www.yoctoproject.org/docs/2.5.3/mega-manual/mega-manual.html#detailed-supported-distros>

2. Create an empty BSP directory and change to it.

3. Unpack BSP metadata:

```
tar xzf /path/to/sources/sources-base*.tar.gz
tar xzf /path/to/sources/sources-meta-kontron-sal28*.tar.gz
```

This will create "sources/" subdirectory populated with metadata layers

4. Set up Yocto build environment:

```
cp sources/meta-kontron-sal28/setup-env ./
source setup-env -m kontron-sal28 -b ./build
```

While this command runs, NXP EULA will be shown. User has to accept it, or BSP build will fail.

5. Once license is accepted, build session is set up in ./build/ subdirectory.

6. Build session could be used to build target system images - which includes kernel image, device tree image and root filesystem image. BSP provides custom image recipe called "sal28-machine-test". It's recommended to start with it. Users already familiar with Yocto can also try building standard Yocto images and/or individual packages.

7. But before building, some extra configuration must be added to "conf/local.conf" file. E.g. "sal28-machine-test" contains binary KEAPI libraries that require agreement with their license. To integrate them into image, following line should be added to "conf/local.conf":

```
LICENSE_FLAGS_WHITELIST += " commercial_libkeapi3 "
```

8. When the build process is completed, the resulted images (kernel, device trees, kernel modules, archived rootfs image and archived sd/usb image) can be found in build/tmp/deploy/images/kontron-sal28/ directory. E.g.:

```
├─ kontron-sal28
│  └─ Image
│     └─ sal28-var2.dtb
│        └─ sal28-var34.dtb
│           └─ sal28-var2-ads2.dtb
│              └─ sal28-var34-ads2.dtb
│                 └─ sal28-var2-s1914.dtb
│                    └─ sal28-var34-s1914.dtb
│                       └─ sal28-var3-ads2-am1280800.dtb
│                          └─ sal28-var3-ads2-b101uan021.dtb
│                             └─ modules-kontron-sal28.tgz
│                                └─ sal28-machine-test-kontron-sal28.tar.gz
│                                   └─ sal28-machine-test-kontron-sal28.wic.gz
```

## 7.2. Deploying created images to SD card or USB flash/disk and booting from it

Note: Kernel image, device tree images and kernel modules are automatically integrated into rootfs and sd/usb images.

1. Attach installation media (SD card or USB flash/disk) to Linux host computer and determine a device node by analyzing system logs:

```
dmesg | tail | grep sd
```

Note: an SD/USB storage should be greater than 4 GB.

2. Extract a previously built SD/USB image from archive:

```
gunzip sal28-machine-test-kontron-sal28.wic.gz
```

Note: more information about WIC images can be found in official Yocto documentation:

<https://www.yoctoproject.org/docs/2.5.3/dev-manual/dev-manual.html#creating-partitioned-images-using-wic>

3. Deploy this image to SD/USB storage using a dd command. E.g.:

```
dd if=sal28-machine-test-kontron-sal28.wic of=/dev/sdb bs=4M oflag=direct
```

Note: all information on SD/USB storage will be erased!

4. Configure serial connection on SER1 port, then connect the installation media to SMARC-sAL28 and power on/reset the board.

5. (Option #1: semi-automatic boot) When a U-Boot prompt will appear, a boot device and device tree should be selected by setting following variables:

boot\_targets, which can be set to:

- ▶ mmc0: to boot from SD;
- ▶ mmc1: to boot from eMMC;
- ▶ nvme0: to boot from NVMe disk;
- ▶ usb0: to boot from USB storage.
- ▶ carrier, which can be set to:
  - ▶ ads2: if variant 3 or variant 4 with Kontron SMARC Evaluation Carrier 2.0 is used;
  - ▶ s1914: if variant 3 or variant 4 with Kontron KBox A-230-LS Carrier is used;
  - ▶ var2\_on\_ads2: if variant 2 on Kontron SMARC Evaluation Carrier 2.0 is used.

E.g. to boot variant 3 on Kontron SMARC Evaluation Carrier 2.0 from SD a following commands should be executed:

```
setenv boot_targets mmc0
setenv carrier ads2
run bootcmd
```

6. (Option #2: manual boot) Interrupt the boot process and check U-boot environment variables with "printenv". If needed, modify paths to kernel image and device tree table. E.g:

```
setenv image /Image
setenv fdt_file /s128-var34-ads2.dtb
```

To boot the board, execute the following commands depending on which type of installation media is used:

- ▶ For USB flash/disk:

```
setenv bootargs root=/dev/sda2 rootwait default_hugepagesz=2m hugepagesz=2m hugepages=256 video=1920x1080
cma=256M
usb start
usb dev 0
fatload usb 0:1 ${fdt_addr_r} ${fdt_file}
fatload usb 0:1 ${kernel_addr_r} ${image}
run hdpload
booti ${kernel_addr_r} - ${fdt_addr_r}
```

- ▶ For SD card:

```
setenv bootargs root=/dev/mmcblk0p2 rootwait default_hugepagesz=2m hugepagesz=2m hugepages=256
video=1920x1080 cma=256M
mmc dev 0
```

```
fatload mmc 0:1 ${fdt_addr_r} ${fdt_file}
fatload mmc 0:1 ${kernel_addr_r} ${image}
run hdpload
booti ${kernel_addr_r} - ${fdt_addr_r}
```

7. After board booted up, login as user root. No password is needed.

For more information on U-boot commands please refer to U-boot user manual here:

<http://www.denx.de/wiki/DULG/Manual>

### 7.3. Booting from NFS server

Note: Setting up NFS booting is highly dependent on Linux distribution used on host. For more details about setting up NFS, DHCP and TFTP daemons consult your distribution documentation.

1. On Linux host computer create a directory for NFS root (say /nfsroot) and extract the rootfs image into it. E.g.:

```
tar xpf /path/to/sal28-machine-test-kontron-sal28.tar.gz -C /nfsroot
```

2. Add NFS root directory to /etc/exports and start NFS server.
3. Copy kernel from extracted rootfs image (Image) into TFTP server root directory ("/var/lib/tftpboot" or "/tftpboot" or "/srv/tftp" depending on Linux distribution). Configure and start TFTP server.
4. Copy an appropriate device tree image (e.g. sl28-var34.dtb) into TFTP server root directory.
5. Configure DHCP server to provide IP configuration for SMARC-sAL28 board.
6. Configure serial connection
7. Power on the board. Interrupt autoboot process by pressing any key on serial console and check U-boot environment variables with "printenv". If needed, modify corresponding variables with setenv command and boot Linux from TFTP server on host by executing:

```
setenv bootargs default_hugepagesz=2m hugepagesz=2m hugepages=256 video=1920x1080-32@60 cma=256M
root=/dev/nfs rw ip=dhcp nfsroot=<host ip>:<path to unpacked rootfs on host>,v3,tcp
setenv serverip <host ip>
setenv ipaddr <sal28 ip>
setenv fdt_file <device tree image copied to tftp>
setenv image <kernel copied to tftp>
tftp ${fdt_addr_r} ${fdt_file}
tftp ${kernel_addr_r} ${image}
booti ${kernel_addr_r} - ${fdt_addr_r}
```

For example:

```
setenv bootargs default_hugepagesz=2m hugepagesz=2m hugepages=256 video=1920x1080-32@60 cma=256M
root=/dev/nfs rw ip=dhcp nfsroot=10.42.0.1:/media/nfsroot/sal28,v3,tcp
setenv serverip 192.168.99.1
setenv ipaddr 192.168.99.101
setenv fdt_file sl28-var34-ads2.dtb
setenv image Image
tftp ${fdt_addr_r} ${fdt_file}
tftp ${kernel_addr_r} ${image}
booti ${kernel_addr_r} - ${fdt_addr_r}
```

8. After board booted up, login as user root. No password is needed.

### 7.4. Deploying created images to on-board eMMC and booting from it

Note: Kernel image, device tree images and kernel modules are automatically built into rootfs image.

1. Boot SMARC-sAL28 either from SD card, USB flash/disk or from NFS as was described above.
2. Deploy the extracted SD/USB image (a wic file) to another USB flash/disk and connect it to the booted SMARC-sAL28 system.
3. Mirror the image from the inserted SD/USB storage to the eMMC device:

```
dd if=/path/to/sal28-machine-test-kontron-sal28.wic of=/dev/mmcblk1 bs=4M oflag=direct
```

Note: all information on eMMC will be erased!

4. Reboot SMARC-sAL28

5. Interrupt the boot process and check U-boot environment variables with "printenv". If needed, modify paths to kernel image and device tree table. E.g:

```
setenv image /Image
setenv fdt_file /sl28-var34-ads2.dtb
```

6. Execute the following commands:

```
setenv bootargs root=/dev/mmcblk1p2 rootwait default_hugepagesz=2m hugepagesz=2m hugepages=256
video=1920x1080 cma=256M
mmc dev 1
fatload mmc 1:1 ${fdt_addr_r} ${fdt_file}
fatload mmc 1:1 ${kernel_addr_r} ${image}
run hdpload
booti ${kernel_addr_r} - ${fdt_addr_r}
```

7. After board booted up, login as user root. No password is needed.

## 8/ Implementation Notes

### 8.1. GPIO

SMARC GPIO0-GPIO11 lines are mapped in Linux in the following way:

Table 27: GPIO

Name	Legacy interface: "/sys/class/gpio"	Modern interface: "/dev/gpiochip"
GPIO0	gpio400	GPIO0_CAM0_PWR_N
GPIO1	gpio401	GPIO1_CAM1_PWR_N
GPIO2	gpio402	GPIO2_CAM0_RST_N
GPIO3	gpio403	GPIO3_CAM1_RST_N
GPIO4	gpio404	GPIO4_HDA_RST_N
GPIO5	gpio405	GPIO5_PWM_OUT
GPIO6	gpio406	GPIO6_TACHIN
GPIO7	gpio407	GPIO7
GPIO8	gpio392	GPIO8
GPIO9	gpio393	GPIO9
GPIO10	gpio394	GPIO10
GPIO11	gpio395	GPIO11

These GPIOs could be controlled either over sysfs (legacy approach), as documented in <https://elixir.bootlin.com/linux/v4.14/source/Documentation/gpio/sysfs.txt>. For example, following shell script blinks carrier's LED connected to GPIO5 line:

```
echo 405 > /sys/class/gpio/export
echo out > /sys/class/gpio/gpio405/direction
while true; do
echo 0 > /sys/class/gpio/gpio405/value
sleep 1
echo 1 > /sys/class/gpio/gpio405/value
sleep 1
done
```

Or via modern "/dev/gpiochip" interface, information about which and corresponding examples/tools can be found at following links:

<https://elixir.bootlin.com/linux/v4.14/source/include/uapi/linux/gpio.h>

<https://elixir.bootlin.com/linux/v4.14/source/tools/gpio>

<https://git.kernel.org/pub/scm/libs/libgpiod/libgpiod.git/tree/README?h=v1.4.x>

#### NOTICE

GPIO5 and GPIO6 are shared with PWM\_OUT and TACHIN signals, so one function (fan, gpio) can be used at the same time.

Also the gpio lines support interrupt handling from userspace. For this purpose the attributes "edge" and "value" in sysfs should be used. There is a simple program in C language which gratefully illustrate how this interface may be used by developers: <https://developer.ridgerun.com/wiki/index.php?title=Gpio-int-test.c>



Plus a gpiomon tool from libgpiod tools, which is provided as part of the BSP, can be used to monitor the GPIO interrupts. E.g.:

```
# gpiofind GPIO7
gpiochip4 7
# gpiomon gpiochip4 7
```

## 8.2. UART

SMARC serial ports are enabled via UART ports on LS1028A SoC. Under Linux:

- ▶ SER0 maps to /dev/ttyLP0 Notes: RTS and CTS are available;
- ▶ SER1 maps to /dev/ttyS0 Notes: RX and TX only, Console port;
- ▶ SER3 maps to /dev/ttyS1 Notes: RX and TX only

LP-UART supports operation in half-duplex mode. For example, in case of KBox A-230-LS carrier board following options can be configured via device tree:

- ▶ RS232:

```
&cpld_gpio1 {
    rs485-gpio {
        gpio-hog;
        gpios = <0 GPIO_ACTIVE_HIGH>;
        output-low;
    };
    rs232-gpio {
        gpio-hog;
        gpios = <1 GPIO_ACTIVE_HIGH>;
        output-low;
    };
};
&lpuart1 {
};
```

- ▶ RS485 half-duplex (2-wires):

```
&cpld_gpio1 {
    rs485-gpio {
        gpio-hog;
        gpios = <0 GPIO_ACTIVE_HIGH>;
        output-high;
    };
    rs232-gpio {
        gpio-hog;
        gpios = <1 GPIO_ACTIVE_HIGH>;
        output-high;
    };
};
&lpuart1 {
    rs485, rts-low-polarity;
    linux, rs485-enabled-at-boot-time;
};
```

- ▶ RS485 full-duplex (4-wires):

```
&cpld_gpio1 {
    rs485-gpio {
        gpio-hog;
        gpios = <0 GPIO_ACTIVE_HIGH>;
        output-low;
    };
    rs232-gpio {
        gpio-hog;
        gpios = <1 GPIO_ACTIVE_HIGH>;
        output-high;
    };
};
```

```
};
&lpuart1 {
    rs485, rts-low-polarity;
    linux, rs485-enabled-at-boot-time;
};
```

### 8.3. PCI

In case if the optimization/customization of the BSP kernel, it is necessary to make sure that CONFIG\_PCIE\_DW\_PLAT is still enabled in kernel config. Otherwise the PCIe controller won't be initialized properly and particular PCIe Gen2 devices won't be enumerated and detected automatically during boot.

### 8.4. I2C Buses

I2C\_PM and I2C\_GP buses on SMARC carrier are mapped to i2c-1 and i2c-2 devices accordingly:

```
# i2cdetect -l
i2c-1  i2c          2030000. i2c          I2C adapter
i2c-2  i2c          2040000. i2c          I2C adapter
```

These devices can be accessed using a standard dev-interface API:

<https://elixir.bootlin.com/linux/v4.14/source/Documentation/i2c/dev-interface>

### 8.5. SPI Buses

SPIO on SMARC connector is an "ordinary" SPI bus governed by Freescale DSPI controller/driver. To make this bus available in KEAPI, an spidev driver is bound in sl28.dts device tree file:

```
&dspi2 {
    bus-num = <2>;
    status = "okay" ;
    dspidev@0 {
        compatible = "spidev" ;
        reg = <0>;
        spi-max-frequency = <50000000>;
    };
};
```

As a result, the bus can be accessed via standard dev-interface as /dev/spidev2:

<https://elixir.bootlin.com/linux/v4.14/source/Documentation/spi/spidev>

ESPI on SMARC connector is handled by Flex SPI controller/driver. This controller is optimized for SPI-NOR flash reading usecase and is not suitable for generic SPI transfers of arbitrary length. So devices other than flash are not supported.

The BSP provides an MTD interface for SPI-NOR flash chips connected to ESPI bus. User needs to adjust DTS file and describe connected chips in fspi node in the device tree. Here's example DTS snippet for Winbond W25Q128FW chip:

```
&fspi {
    flash1: w25q128fw@1 {
        # address-cells = <1>;
        # size-cells = <1>;
        compatible = "jedec, spi-nor" ;
        m25p, fast-read;
        spi-max-frequency = <30000000>;
        reg = <1>;
        /* The following setting enables 1-1-8 (CMD-ADDR-DATA) mode */
        spi-rx-bus-width = <4>; /* 4 SPI Rx lines */
        spi-tx-bus-width = <4>; /* 4 SPI Tx line */
        status = "okay" ;
    };
};
```

reg property should correspond to cs: 0 for ESPI\_CS0#, 1 for ESPI\_CS1#

#### **NOTICE**

The BSP provides a read-only access to on-module SPI flash with U-Boot boot loader.

The BSP provides a read-only access to on-module SPI flash with U-Boot boot loader, and which is located at ESPI bus at CS0, via MTD interface:

```
mtd0: 00010000 00001000 "rcw"
mtd1: 000f0000 00001000 "failsafe bootloader"
mtd2: 00040000 00001000 "failsafe DP firmware"
mtd3: 000a0000 00001000 "failsafe PPA firmware"
mtd4: 00020000 00001000 "reserved"
mtd5: 00010000 00001000 "configuration store"
mtd6: 000f0000 00001000 "bootloader"
mtd7: 00040000 00001000 "DP firmware"
mtd8: 000a0000 00001000 "PPA firmware"
mtd9: 00020000 00001000 "bootloader environment"
```

## 8.6. Watchdog

Two watchdog devices are supported by the BSP:

- ▶ /dev/watchdog0 and /dev/watchdog1 are additional watchdog timers ( /dev/watchdog0 is also available as legacy /dev/watchdog), which correspond to built-in watchdog device in LS1028A SoC;
- ▶ /dev/watchdog2 is a main watchdog timer, which corresponds to watchdog device in CPLD. This watchdog device is able to reset the CPU and to assert WDT\_TIME\_OUT# line on SMARC connector.

Note that KEAPI provides access only to the CPLD watchdog (/dev/watchdog2). But it can be easily changed by adjusting a corresponding config: /etc/keapi/watchdog.conf. Please refer to /etc/keapi/watchdog\_cpld.conf and /etc/keapi/watchdog\_soc.conf.

## 8.7. CAN

FlexCAN controller controller and corresponding driver support operation in two modes: CAN FD and CAN 2.0. By default a CAN FD mode, which may not be supported by some devices, is activated. To switch to CAN 2.0 mode, following commands can be used:

```
# ifconfig can0 down
# ip link set can0 type can fd off
# ip link set can0 type can bitrate 1000000 #NOTE: bitrate should be adjusted
# ifconfig can0 up
```

## 8.8. Video Output (DP and LVDS)

Depending on type of SMARC-sAL28 module, either DP or LVDS output is supported.

To activate a DP output, following actions should be performed:

- ▶ DP firmware should be loaded in U-Boot before loading Linux. i.e. following command should be executed in U-Boot prompt:

```
run hdpload
```

- ▶ an "ordinary" dtb file (sl28-var34-ads2.dtb) should be loaded;
- ▶ an appropriate resolution should be passed to kernel via cmdline, e.g.:

```
default_hugepagesz=2m hugepagesz=2m hugepages=256 video=1920x1080-32@60 cma=256M root=/dev/nfs rw ip=dhcp
```

- ▶ the same resolution should be defined for HDMI-A-1 output in /etc/xdg/weston/weston.ini, e.g.:

```
[core]
idle-time=0
[output]
name=HDMI-A-1
mode=1920x1080@60
[screen-share]
command=/usr/bin/weston --backend=rdp-backend. so --shell=full-screen-shell. so --no-clients-resize
```

- ▶ the list of supported resolution can be found in /var/log/weston.log

In the current version of the BSP, only two LVDS displays are supported: AUO B101UAN02.1 (1920x1200) and AM-1280800N4TZQ (1280x800). The same actions as for DP output above should be performed to activate them, except that a special dtb file should be used: either `sl28-var3-ads2-b101uan021.dtb` or `sl28-var3-ads2-am1280800.dtb` depending on the model of connected display.

Instructions and examples how to add support of another LVDS displays will be provided in future versions of the document.

## 8.9. Fan Monitoring and Control

The BSP provides a standard hwmon interface for PWM\_OUT and TACHIN signals:

<https://elixir.bootlin.com/linux/latest/source/Documentation/hwmon/sysfs-interface.rst#L335>

<https://elixir.bootlin.com/linux/latest/source/Documentation/hwmon/sysfs-interface.rst#L248>

But these signals are shared with GPIO5 and GPIO6:

- ▶ GPIO5 pin is configured as GPIO by default, and:
- ▶ following commands can be executed to enable PWM\_OUT instead:

```
echo 0 > /sys/class/pwm/pwmchip0/export
echo 1 > /sys/class/pwm/pwmchip0/pwm0/enable
```

- ▶ to disable PWM\_OUT and enable GPIO5 again:

```
echo 0 > /sys/class/pwm/pwmchip0/pwm0/enable
```

- ▶ By contrast, GPIO6 pin is visible both as a TACHIN and as GPIO, but only one function (fan, gpio) should be used at a time:
- ▶ to disable a hwmon interface for TACHIN, a device tree should be adjusted as follows:

```
fan@b {
    compatible = "kontron,sl28cp1d-fan";
    reg = <0xb>;
    status = "disabled" ;
};
```

- ▶ in case if TACHIN is used, corresponding GPIO pin should be configured as INPUT and shouldn't be accessed.

## 8.10. Thermal Management

### 8.10.1. Heatspreader and Cooling Solutions

A heatspreader plate assembly is available from Kontron for the SMARC-sAL28. The heatspreader plate on top of this assembly is NOT a heat sink. The heatspreader works as a thermal interface to be use with a heat sink or external cooling devices.

External cooling must be provided to maintain the heatspreader plate at proper operating temperatures. Under worst-case conditions, the cooling mechanism must maintain an ambient air temperature and the heatspreader plate's surface temperature must remain under the maximum temperature range.

### 8.10.2. Operating with Kontron Heatspreader Plate (HSP) Assembly

The operating temperature defines two requirements:

- ▶ Maximum ambient temperature with ambient being the air surrounding the module
- ▶ Maximum measurable temperature on any spot on the heatspreader's surface

The heatspreader is tested for the following temperature specifications.

Table 28: Heatspreader Test Temperature Specifications

Temperature Specification	Validation requirements
Commercial Grade	at 60°C HSP temperature the CPU @ 100% load needs to run at nominal frequency
Industrial Grade by screening (E2S)	at 85°C HSP temperature the CPU @ 50% load is allowed to start throttling for thermal protection

### 8.10.3. Operating without Kontron Heatspreader Plate Assembly

The operating temperature is the maximum measurable temperature on any spot on the module's surface.

#### NOTICE

The CPU is configured, that it starts to throttle its frequency to 647 MHz, when a CPU temperature of 85°C is reached.

## 8.11. TSN Switch

To evaluate the functionality of TSN switch:

- ▶ A Quad PHY should be connected to QSGMI interface, which is routed to PCIE\_D pins of SMARC connector. Plus this PHY should be enabled in device tree. In case of Kontron SMARC S1914 carrier board, it can be achieved by loading `sl28-*-s1914.dtb`.
- ▶ When Linux is booted, the interfaces of TSN switch should be brought-up and aggregated into bridge:

```
# ip link add name br0 type bridge
# ifconfig br0 up
# ip link set swp0 master br0
# ip link set swp1 master br0
# ip link set swp2 master br0
# ip link set swp3 master br0
# ip link set swp4 master br0
# ip link set swp5 master br0
# ifconfig swp0 up
# ifconfig swp1 up
# ifconfig swp2 up
# ifconfig swp3 up
# ifconfig swp4 up
# ifconfig swp5 up
# ifconfig eno2 up
# ifconfig eno3 up
```

- ▶ Afterwards it should be possible to assign an IP address to br0 device and communicate with SMARC-sAL28 over any port of TSN switch using this IP address:

```
# ifconfig br0 10.42.1.10
# ping 10.42.1.1 -c 5
```

#### NOTICE

Despite the fact that `linuxptp` package is integrated into the BSP, the PTP functionality of TSN switch has not been validated yet. For more information about interaction with the TSN switch, please refer to User's Guide for reference Linux BSP for LS1028A from NXP: "Layerscape LS1028A BSP User Guide" or `LS1028ABSPUG.pdf`.

## 9/ Bootloader Operation

### 9.1. Copyrights and Licensing of U-Boot

U-Boot is free Software. It is copyrighted by Wolfgang Denk and many others who contributed code. U-Boot can be redistributed and modified under the terms of version 2 of the GNU General Public (GPL V2) License as published by the Free Software Foundation.

Actual source code of mainline U-Boot and authors of the source can be obtained from the git repository at

- ▶ `git://git.denx.de/u-boot.git`

SMARC-sAL28 bootloader sources are derived work from a dedicated version of mainline U-Boot, e.g v2018.07. As bootloader evolves, the root of the derived work might change to a later version.

#### NOTICE

The source code of U-Boot will be delivered with the standard software package. Additionally the software can be downloaded from Kontron GitHub repository for SMARC-sAL28: <https://github.com/kontron/u-boot-smarc-sAL28.git>

### 9.2. Bootloader Quickstart

The SMARC-sAL28 board comes with U-Boot preinstalled on the QSPI flash device. Follow the steps below to gain access to the bootloader command line (CLI) on your host PC.

- ▶ Connect your host machine to the carrier port connected with the edge connector SER\_0 port of the module. On Kontron SMARC 2.0 carrier this port is named SER\_1.
- ▶ Start a suitable terminal program on your host and attach it to the port connected with the board's serial interface. Configure the serial line using **115200 baud, 8 data bits, 1 stop bit, no parity**.
- ▶ Connect power supply to the carrier and power up.
- ▶ When boot messages appear, press any key to stop automatic boot sequence.

After power on, bootloader boot messages will appear as shown below. There is a 2 second boot delay counter that will try to boot linux OS automatically after expiration. Pressing any key will stop the boot delay counter and enter the bootloader CLI

```
U-Boot SPL 2018.09-g3b96286ea1 (Oct 01 2019 - 00:05:46 +0000)
Initializing DDR...using raw memory timing
SPI boot
Trying to boot from SPI

U-Boot 2018.09-g3b96286ea1 (Oct 01 2019 - 00:05:46 +0000), Build: 401
SoC: LS1028A Rev1.0 (0x870b0110)
Clock Configuration:
  CPU0 (A72):1300 MHz  CPU1 (A72):1300 MHz
  Bus:      400 MHz  DDR:      1600 MT/s
Reset Configuration Word (RCW):
00000000: 34004010 00000030 00000000 00000000
00000010: 00000000 008f0000 0030c000 00000000
00000020: 06200000 00002580 00000000 00019016
00000030: 00000000 00000048 00000000 00000000
00000040: 00000000 00000000 00000000 00000000
00000050: 00000000 00000000 00000000 00000000
00000060: 00000103 00000000 100e7026 00000000
00000070: bb580000 00020000

Model: Kontron SMARC-sAL28 Board
Hardware Variant: Single PHY (3)
RCW: sl28-3-11_q.bin
```

```

DRAM: Detected UDIMM Fixed DDR on board
3.9 GiB
DDR 3.9 GiB (DDR3, 32-bit, CL=11, ECC on)
Using SERDES1 Protocol: 47960 (0xbb58)
PCIe0: pcie@3400000 Root Complex: x1 gen2
PCIe1: pcie@3500000 Root Complex: x1 gen3
CPLD: v17
Waking secondary cores to start from fbd38000
All (2) cores are up.
MMC: FSL_SDHC: 0, FSL_SDHC: 1
Loading Environment from SPI Flash... SF: Detected w25q32dw with page size 256 Bytes, erase size 64 KiB,
total 4 MiB
OK
In: serial
Out: serial
Err: serial
VPD: Using device 0x50 on I2C Bus 2
Net: eth0: enetc#0, eth2: enetc#1, eth8: netc_mdio
Hit any key to stop autoboot: 0

```

### 9.3. Bootloader Commands

The bootloader CLI provides a bunch of powerful commands to control the board, which basically can be grouped into

- ▶ Information Commands
- ▶ Memory Commands
- ▶ Flash Memory Commands
- ▶ Execution Control Commands
- ▶ Download Commands
- ▶ Environment Control Commands
- ▶ Flattened Device Tree Support Commands
- ▶ Storage Device Control Commands
- ▶ File System Support Commands
- ▶ Kontron Command Extensions




---

Typing "help" at the bootloader command line prompt will show up a list of the commands available. Typing "help <command>" will show specific command help. Further help can be found under <https://www.denx.de/wiki/view/DULG/UBoot>

---

On the SMARC\_sAL28 bootloader, the powerful hush shell is enabled, which is similar to Bourne shell and provides features similar to a linux shell:

- ▶ Control structures (if ... then ... else ... fi etc.)
- ▶ Command line completion
- ▶ Command line editing
- ▶ Command line history up to 20 entries
- ▶ Local environment variables

### 9.4. Kontron Bootloader Command Extensions

Kontron's implementation of U-Boot includes certain enhancements to provide board specific functions. They are not part of standard U-Boot as maintained by DENX. The following table provides a complete listing of all Kontron command extensions on the SMARC-sAL28.

Table 29: Bootloader Command Extensions

Command	Description
kboardinfo	Kontron Board Information - Displays a summary of board and configuration information
wdt	Start and control CPLD and LS1028A core0 1 CPU watchdog

### 9.4.1. kboardinfo - Kontron Board Information

The "kboardinfo" command shows a summary of board serialization data gathered from the system EEPROM.

```

=> kboardinfo
Manufacturer:      Kontron Europe GmbH
Product name:     SMARC-sAL28
Material number:  51011-0408-13-2-3
Serial number:    USD0C0001
MAC0 (ethaddr):  00:a0:a5:5c:6b:3a
MAC1 (eth1addr): 00:a0:a5:5c:6b:3b
MAC2 (eth2addr): 00:a0:a5:5c:6b:3c
MAC3 (eth3addr): 00:a0:a5:5c:6b:3d
MAC4 (eth4addr): 00:a0:a5:5c:6b:3e
MAC5 (eth5addr): 00:a0:a5:5c:6b:3f
MAC6 (eth6addr): 00:a0:a5:5c:6b:40
MAC7 (eth7addr): 00:a0:a5:5c:6b:41
Manufacturer Date: 08/26/2019
Revision:         A00
Boot Counter:     3362

```

### 9.4.2. Wdt – CPU Watchdog Control

The wdt command is used to control the CPLD and core0/1 LS1028A CPU internal watchdog.

#### Syntax:

```

=> help wdt
wdt - Watchdog sub-system

Usage:
wdt list - list watchdog devices
wdt dev [<name>] - get/set current watchdog device
wdt start <timeout ms> [flags] - start watchdog timer
wdt stop - stop watchdog timer
wdt reset - reset watchdog timer
wdt expire [flags] - expire watchdog timer immediately

```

## 9.5. Bootloader Environment

The bootloader environment is used to control bootloader and OS startup behavior. Environment variables can be used to control boot timing (e.g. bootdelay), interface properties (e.g. baudrate, ethact) or they define memory locations where OS images are stored before boot (e.g. loadaddr, fdt\_addr). In addition, bootloader shell commands can be combined to environment scripts.

The redundant bootloader environment is permanently stored in the QSPI flash device at offset 0x3E0000 and 0x3F0000. During bootloader operation, the environment is held in RAM memory and can be modified and written back to persistent storage.

Bootloader commands to modify the environment are summed up under the "env" command group:

[www.kontron.com](http://www.kontron.com)



- ▶ `env default [-f] -a` [forcibly] reset default environment
- ▶ `env default [-f] var [...]` [forcibly] reset variable(s) to their default values
- ▶ `env delete [-f] var [...]` [forcibly] delete variable(s)
- ▶ `env edit name` edit environment variable
- ▶ `env exists name` tests for existence of variable
- ▶ `env exists name` tests for existence of variable
- ▶ `env export [-t | -b | -c] [-s size] addr [var ...]` export environment
- ▶ `env grep [-e] [-n | -v | -b] string [...]` search environment
- ▶ `env import [-d] [-t [-r] | -b | -c] addr [size] [var ...]` import environment
- ▶ `env print [-a | name ...]` print environment
- ▶ `env run var [...]` run commands in an environment variable
- ▶ `env save` save environment
- ▶ `env set [-f] name [arg ...]`

However, the legacy commands for environment handling are still available:

- ▶ "setenv",
- ▶ "editenv",
- ▶ "printenv"
- ▶ "saveenv".

U-Boot standard environment variables are set up for the SMARC\_sAL28 module as shown below.

**Table 30: Standard Environment Variables**

Variable	Value	Description
baudrate	115200	Serial line baudrate
bootcmd	run hdpload; run distro_bootcmd	Try booting from devices defined in the boot_targets variable
bootdelay	2	Wait 2 seconds before executing bootcmd
boot_targets	mmc1 mmc0 nvme0 usb0 dhcp pxe	Boot devices used by distro_bootcmd to boot from
loadaddr	0x81000000	Default memory location for OS boot

A typical user modification would be to set the variable "bootcmd" to change OS boot commands.

## 9.6. Bootloader Environment Update

On the SMARC-sAL28 it is possible to update the U-Boot environment separately.

This enables the user to either update from a previous version of the official Kontron sAL28 U-Boot environment (default U-Boot settings), or restore the default in case of problems.

Update procedure:

- ▶ Download the official sAL28 U-Boot environment from the Kontron EMD Customer Section.
- ▶ Put the file into the root directory of a FAT or EXT formatted USB drive.
- ▶ Start the sAL28 system and stop the boot process at the U-Boot prompt.
- ▶ Run the following commands to load the file and flash it into the correct flash memory address (example for R10):

```
usb start && load usb 0:1 $loadaddr NXP LS1028-env-r10.bin
sf probe && sf update $loadaddr 0x3e0000 $filesize
```

- ▶ After reset the updated environment will be active.

## 9.7. Bootloader Mass Storage Support

U-Boot provides support to read and write from mass storage devices like

- ▶ QSPI flash
- ▶ SD card
- ▶ USB thumb device

### 9.7.1. QSPI flash

QSPI flash is accessed using the "sf" command

**Example:** Load one sector (64K) from SPI flash

```
=> sf probe 0
=> sf read ${loadaddr} 0 10000
```

### 9.7.2. SD Card and eMMC Devices

eMMC and SD card are accessed using the "mmc" command

**Example:** Load 256 blocks from eMMC

```
=> mmc dev 1
=> mmc read ${loadaddr} 0 100
```

### 9.7.3. USB Storage Device

USB storage devices are accessed using "usb" command

**Example:** Load bootloader update file from USB thumb device

```
=> usb start
=> usb dev 0
=> fatload usb 0:1 update_NXP_LS1028_spl/u-boot-NXP_LS1028_spl.bin
```

## 9.8. Bootloader File System Support

U-Boot for the SMARC\_sAL28 provides support for FAT and EXT4 file systems. EXT4 support also includes EXT2 and EXT3 formatted file systems. There are file system specific commands available to list file system contents (ext2ls, fatls) and load a given file into board memory (ext2load, fatload). However, U-Boot also provides generic commands ("ls" and "load"), that will detect the file system on the device and use appropriate file system functions automatically.

**Example:** Show/boot folder contents from SD card file system

```
=> ls mmc 0:1 /boot
<DIR>    4096 .
<DIR>    4096 ..
<SYM>     48 imx7d-sAL28-ld101-m4.dtb
         44034 devicetree-zImage-imx7d-sAL28-ld101-m4.dtb
         43986 devicetree-zImage-imx7d-sAL28-ld101.dtb
<SYM>     33 zImage
<SYM>     45 imx7d-sAL28-ld101.dtb
<SYM>     45 imx7s-sAL28-ld101.dtb
         6376512 zImage-4.1.29-fslc+g59b38c3
         43998 devicetree-zImage-imx7s-sAL28-ld101.dtb

=> load mmc 0:1 ${loadaddr} /boot/zImage
6376512 bytes read in 536 ms (11.3 MiB/s)
```

## 9.9. Bootloader Network Support

U-Boot provides support for both onboard Ethernet interfaces. The current interface can be selected by setting "ethact" environment variable to either "enetc#0" or "enetc#1".

Board specific MAC addresses are read from EEPROM during startup and environment variables are set automatically. In case EEPROM contents is missing or corrupted, a "random" MAC address will be set to "ethaddr".

In case that the current network interface is attached to a network providing a DHCP server, an IP address can be gathered using "bootp" or "dhcp" commands.

After that, a file from a tftp server can be copied to memory using the "tftpboot" command.

### Example:

```
=> bootp
=> tftpboot ${loadaddr} <filename>
```

## 9.10. Bootloader Boot Counter

The module EEPROM device contents implements a SMBIOS Running-time data block (type 161) as defined in the KEU EEPROM Specification Rev. 1.4. The running-time data block structure implements a 64bit boot counter. U-Boot on the SMARC\_sAL28 module will read the current boot counter value and increment it on every boot cycle. Current boot counter is shown as part of the information shown by the "kboardinfo" command (see description of kboardinfo).

## 9.11. U-boot Files for the Kontron SMARC sAL28 Module on Github.com

You can find the last program code under <https://github.com/kontron/u-boot-smarc-sAL28.git>.

## 10/ Technical Support

For technical support contact our Support Department:

E-mail: [support@kontron.com](mailto:support@kontron.com)

Phone: +49-821-4086-888

Make sure you have the following information available when you call:

Product ID Number (PN),

Serial Number (SN)




---

The serial number can be found on the Type Label, located on the product's rear side.

---

Be ready to explain the nature of your problem to the service technician.

### 10.1. Warranty

Due to their limited service life, parts that by their nature are subject to a particularly high degree of wear (wearing parts) are excluded from the warranty beyond that provided by law. This applies to the CMOS battery, for example.




---

If there is a protection label on your product, then the warranty is lost if the product is opened.

---

### 10.2. Returning Defective Merchandise

All equipment returned to Kontron must have a Return of Material Authorization (RMA) number assigned exclusively by Kontron. Kontron cannot be held responsible for any loss or damage caused to the equipment received without an RMA number. The buyer accepts responsibility for all freight charges for the return of goods to Kontron's designated facility. Kontron will pay the return freight charges back to the buyer's location in the event that the equipment is repaired or replaced within the stipulated warranty period. Follow these steps before returning any product to Kontron.

1. Visit the RMA Information website:  
<http://www.kontron.com/support-and-services/support/rma-information>

Download the RMA Request sheet for **Kontron Europe GmbH** and fill out the form. Take care to include a short detailed description of the observed problem or failure and to include the product identification Information (Name of product, Product number and Serial number). If a delivery includes more than one product, fill out the above information in the RMA Request form for each product.

2. Send the completed RMA-Request form to the fax or email address given below at Kontron Europe GmbH. Kontron will provide an RMA-Number.

Kontron Europe GmbH  
RMA Support  
Phone: +49 (0) 821 4086-0  
Fax: +49 (0) 821 4086 111  
Email: [service@kontron.com](mailto:service@kontron.com)

3. The goods for repair must be packed properly for shipping, considering shock and ESD protection.



---

**Goods returned to Kontron Europe GmbH in non-proper packaging will be considered as customer caused faults and cannot be accepted as warranty repairs.**

---

4. Include the RMA-Number with the shipping paperwork and send the product to the delivery address provided in the RMA form or received from Kontron RMA Support.

## List of Acronyms

CPLD	Complex Programmable Logic Devices
CSI	Camera Serial Interface
DTE	Data Terminal Equipment
DSI	Display Serial Interface
DCE	Data Communications Equipment
eCSPI	enhanced Configurable Synchronous Programmable serial Interface
eCSPI	enhanced Configurable Synchronous Programmable serial Interface
eDP	embedded Display Port
EMC	Electromagnetic Compatibility
EMI	Electromagnetic Interference
eMMC	embedded Multimedia Card
EPDC	Electronic Paper Display Controller
ESD	Electrostatic Discharge
GPIO	General-purpose input/output
HDA	High Definition Audio
HDMI	Integrated High Definition Multimedia Interface
I2S	Inter-IC Sound
KPP	Key Pad Port
LPDDR	Low Power DDR
LVDS	Low Voltage Differential Signalling
MIPI	Mobile Industry Processor Interface
MLC	Multi-level Cell
pSLC	pseudo Single Level Cell
SDIO	Secure Digital Input Output
SMARC	Smart Mobility ARChitecture
SMBus	System Management Bus
SoC	System on Chip
TPM	Trusted Platform Module
UART	Universal Asynchronous Receiver Transmitter



## About Kontron – Member of the S&T Group

Kontron is a global leader in Embedded Computing Technology (ECT). As a part of technology group S&T, Kontron offers a combined portfolio of secure hardware, middleware and services for Internet of Things (IoT) and Industry 4.0 applications. With its standard products and tailor-made solutions based on highly reliable state-of-the-art embedded technologies, Kontron provides secure and innovative applications for a variety of industries. As a result, customers benefit from accelerated time-to-market, reduced total cost of ownership, product longevity and the best fully integrated applications overall.

For more information, please visit: <http://www.kontron.com/>



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